



### **General Description**

The MAX16047A/MAX16049A EEPROM-configurable system managers monitor, sequence, and track multiple system voltages. The MAX16047A manages up to twelve system voltages simultaneously, and the MAX16049A manages up to eight supply voltages. These devices integrate an analog-to-digital converter (ADC) for monitoring supply voltages, and configurable outputs for sequencing and tracking supplies (during power-up and powerdown). Nonvolatile EEPROM registers are configurable for storing upper and lower voltage limits, setting timing and sequencing requirements, and for storing critical fault data for read back following failures.

An internal 1% accurate 10-bit ADC measures each input and compares the result to one upper, one lower, and one selectable upper or lower limit. A fault signal asserts when a monitored voltage falls outside the set limits. Up to three independent fault output signals are configurable to assert under various fault conditions.

The integrated sequencer/tracker allows precise control over the power-up and power-down order of up to twelve (MAX16047A) or up to eight (MAX16049A) power supplies. Four channels (EN\_OUT1-EN\_OUT4) support closed-loop tracking using external series MOSFETs. Six outputs (EN OUT1-EN OUT6) are configurable with charge-pump outputs to directly drive MOSFETs without closed-loop tracking.

The MAX16047A/MAX16049A include six programmable general-purpose inputs/outputs (GPIOs). In addition to serving as EEPROM-configurable I/O pins, the GPIOs are also configurable as dedicated fault outputs, as a watchdog input or output (WDI/WDO), or as a manual reset (MR).

The MAX16047A/MAX16049A feature two methods of fault management for recording information during critical fault events. The fault logger records a failure in the internal EEPROM and sets a lock bit protecting the stored fault data from accidental erasure.

An I<sup>2</sup>C/SMBus<sup>™</sup>-compatible or a JTAG serial interface configures the MAX16047A/MAX16049A. These devices are offered in a 56-pin, 8mm x 8mm TQFN package and are fully specified from -40°C to +125°C.

Features

- ♦ Operate from 3V to 14V
- ♦ 1% Accurate 10-Bit ADC Monitors 12/8 Inputs
- ♦ 12/8 Monitored Inputs with One Overvoltage/ One Undervoltage/One Selectable Limit
- ♦ Nonvolatile Fault Event Logger
- **♦** Power-Up and Power-Down Sequencing
- ♦ 12/8 Outputs for Sequencing/Power-Good **Indicators**
- **♦** Closed-Loop Tracking for Up to Four Channels
- **♦ Two Programmable Fault Outputs and One Reset** Output
- ♦ Six General-Purpose Input/Outputs Configurable as: **Dedicated Fault Output Watchdog Timer Function Manual Reset**
- ♦ I<sup>2</sup>C/SMBus-Compatible and JTAG Interface
- **♦** EEPROM-Configurable Time Delays and Thresholds
- ♦ 100 Bytes of Internal User EEPROM
- ♦ 56-Pin (8mm x 8mm) TQFN Package
- ♦ -40°C to +125°C Operating Temperature Range

**Applications** 

Servers

Workstations

Storage Systems

Networking/Telecom

### **Ordering Information**

PART	TEMP RANGE	PIN-PACKAGE
<b>MAX16047A</b> TN+	-40°C to +125°C	56 TQFN-EP*
MAX16049ATN+	-40°C to +125°C	56 TQFN-EP*

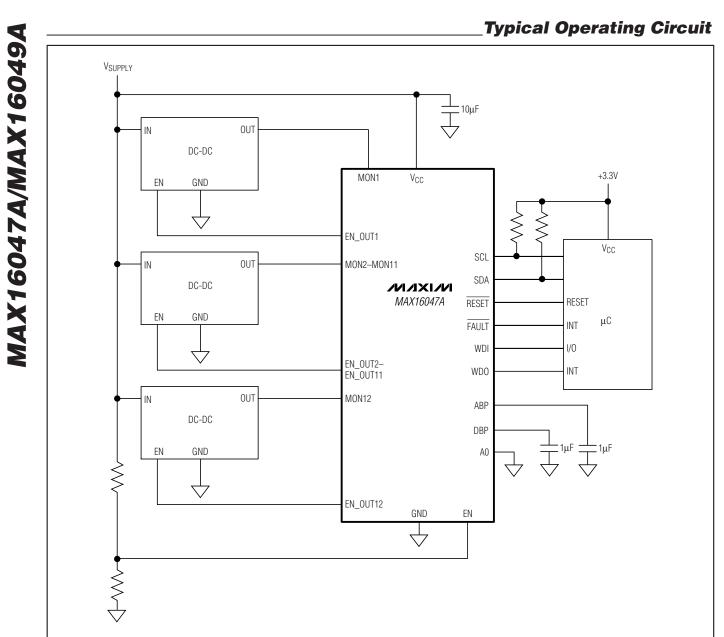
<sup>+</sup>Denotes a lead(Pb)-free/RoHS-compliant package.

SMBus is a trademark of Intel Corp.

Selector Guide appears at end of data sheet.

Maxim Integrated Products 1

<sup>\*</sup>EP = Exposed Pad.



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### **ABSOLUTE MAXIMUM RATINGS**

V <sub>CC</sub> to GND0.3V to +15V
EN, MON_, SCL, SDA, A00.3V to +6V
GPIO_, EN_OUT7-EN_OUT12, RESET
(configured as open drain) to GND0.3V to +6V
EN_OUT1-EN_OUT6
(configured as open-drain) to GND0.3V to +12V
GPIO_, EN_OUT, RESET
(configured as push-pull) to GND0.3V to (V <sub>DBP</sub> + 0.3V)
DBP, ABP to GND0.3V to the lower of 3V and $(V_{CC} + 0.3V)$
TCK, TMS, TDI0.3V to +3.6V
TDO0.3V to $(V_{DBP} + 0.3V)$
EN_OUT1-EN_OUT6
(configured as charge pump)0.3V to (VMON1-6 + 6V)

Continuous Current (all pins)	±20mA
Continuous Power Dissipation (T <sub>A</sub> = +70°C) 56-Pin TQFN (derate 47.6mW/°C above +70°C) Thermal Resistance	3810mW*
θ <sub>J</sub> Α	
θJC	0.6°C/W
Operating Temperature Range40	
Junction Temperature	+150°C
Storage Temperature Range65°	C to +150°C
Lead Temperature (soldering, 10s)	+300°C
Soldering Temperature (reflow)	

<sup>\*</sup>As per JEDEC 51 Standard, Multilayer Board (PCB).

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### **ELECTRICAL CHARACTERISTICS**

 $(V_{CC} = 3V \text{ to } 14V, T_A = -40^{\circ}\text{C to } + 125^{\circ}\text{C}, \text{ unless otherwise specified.}$  Typical values are at  $V_{CC} = 3.3V, T_A = +25^{\circ}\text{C}.)$  (Note 1)

PARAMETER	SYMBOL	C	CONDITIONS	MIN	TYP	MAX	UNITS
Operating Voltage Range	Vcc	RESET output a	RESET output asserted low				V
Operating voltage hange	VCC			3		14	V
Undervoltage Lockout	V <sub>UVLO</sub>	(Note 2)				2.85	V
Undervoltage-Lockout Hysteresis	UVLO <sub>HYS</sub>				50		mV
Supply Current	Icc	VCC = 14V, VEN output	V <sub>CC</sub> = 14V, V <sub>EN</sub> = 3.3V, no load on any output		3.8	5	mA
DBP Regulator Voltage	$V_{DBP}$	$C_{DBP} = 1\mu F$ , no	load on any output	2.6	2.7	2.8	V
ABP Regulator Voltage	$V_{ABP}$	$C_{ABP} = 1\mu F$ , no	load	2.78	2.88	2.96	V
Boot Time	tBOOT	VCC > VUVLO			0.8	1.5	ms
Internal Timing Accuracy		(Note 3)		-10		+10	%
ADC							
ADC Resolution					10		Bits
	ADCERR	$T_{A = -40^{\circ}\text{C}}$ to $+85^{\circ}\text{C}$	MON_ range set to '00'			0.65	%FSR
			MON_ range set to '01'			0.75	
ADC Total Unadjusted Error			MON_ range set to '10'			0.95	
(Note 4)		$T_{A} = -40^{\circ}C \text{ to}$	MON_ range set to '00'			0.85	
			MON_ range set to '01'			0.95	
		MON_ range set to '10'				1.15	
ADC Integral Nonlinearity	ADCINL					0.8	LSB
ADC Differential Nonlinearity	ADC <sub>DNL</sub>		<u> </u>			0.8	LSB
ADC Total Monitoring Cycle Time	tCYCLE	All channels mo no MON_ fault of	onitored, detected (Note 5)		120	150	μs
MON I have through a domain	Du	MON1-MON4		46.5		100	1.0
MON_ Input Impedance	R <sub>IN</sub>	MON5-MON12		65		140	kΩ

### **ELECTRICAL CHARACTERISTICS (continued)**

(V<sub>CC</sub> = 3V to 14V, T<sub>A</sub> = -40°C to +85°C, unless otherwise specified. Typical values are at V<sub>CC</sub> = 3.3V, T<sub>A</sub> = +25°C.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	
		MON_ range set to '00' in r0Fh-r11h		5.6			
ADC MON_ Ranges	ADC <sub>RNG</sub>	MON_ range set to '01' in r0Fh-r11h		2.8		V	
		MON_ range set to '10' in r0Fh-r11h		1.4			
		MON_ range set to '00' in r0Fh-r11h		5.46			
ADC LSB Step Size	ADCLSB	MON_ range set to '01' in r0Fh-r11h		2.73		mV	
		MON_ range set to '10' in r0Fh-r11h		1.36			
EN Input-Voltage Threshold	VTH_EN_R	EN voltage rising		0.525		V	
EN Imput-voltage imreshold	VTH_EN_F	EN voltage falling	0.486	0.500	0.517	V	
EN Input Current	I <sub>EN</sub>		-0.5		+0.5	μΑ	
EN Input Voltage Range			0		5.5	V	
CLOSED-LOOP TRACKING							
Tracking Differential Voltage Stop Ramp	VTRK	VINS_ > VTH_PL, VINS_ < VTH_PG		150		mV	
Tracking Differential Voltage Hysteresis				20		%V <sub>TRK</sub>	
Tracking Differential Fault Voltage	V <sub>TRK_F</sub>	V <sub>INS_</sub> > V <sub>TH_PL</sub> , V <sub>INS_</sub> < V <sub>TH_PG</sub>	280	325	370	mV	
	TRK <sub>SLEW</sub>	Slew-rate register set to '00'	640	800	960	V/s	
Track/Sequence Slew-Rate		Slew-rate register set to '01'	320	400	480		
Rising or Falling		Slew-rate register set to '10'	150	200	230		
		Slew-rate register set to '11'	70	100	115		
		Power-good register set to '00,' VMON_ = 3.5V	94	95	96		
W0 D 0 17 11	.,	Power-good register set to '01,' VMON_ = 3.5V	91.5	92.5	93.5	0/1/	
INS_ Power-Good Threshold	VTH_PG	Power-good register set to '10,' VMON_ = 3.5V	89	90	91	%VMON_	
		Power-good register set to '11,' VMON_ = 3.5V	86.5	87.5	88.5		
Power-Good Threshold Hysteresis	V <sub>PG_HYS</sub>			0.5		%V <sub>TH_PC</sub>	
Power-Low Threshold	V <sub>TH_PL</sub>	INS_ falling	125	142	160	mV	
Power-Low Hysteresis	VTH_PL_HYS			10		mV	
GPIO_ Input Impedance	GPIOINR	GPIO_ configured as INS_	75	100	145	kΩ	
INS_ to GND Pulldown Impedance when Enabled	INS <sub>RPD</sub>	V <sub>INS</sub> _ = 2V		100		Ω	

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### **ELECTRICAL CHARACTERISTICS (continued)**

 $(V_{CC} = 3V \text{ to } 14V, T_A = -40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C}, \text{ unless otherwise specified. Typical values are at } V_{CC} = 3.3V, T_A = +25^{\circ}\text{C.})$  (Note 1)

PARAMETER	SYMBOL	C	ONDITIONS	MIN	TYP	MAX	UNITS	
OUTPUTS (EN_OUT_, RESET, GPIO_)								
Output-Voltage Low	VoL	Isink = 2mA				0.4	V	
Output-Voltage High (Push-Pull)		ISOURCE = 100µ	A	2.4			V	
						1		
Output Leakage (Open Drain)	lout_lkg	GPIO1-GPIO4, \	/ <sub>GPIO_</sub> = 3.3V		1		μΑ	
		GPIO1-GPIO4, \	/ <sub>GPIO_</sub> = 5V			23		
EN_OUT_ Overdrive (Charge Pump) (EN_OUT1 to EN_OUT6 Only) Volts above V <sub>MON</sub> _	V <sub>OV</sub>	I <sub>GATE</sub> = 0.5μA		4.6	5.1	5.6	V	
EN_OUT_ Pullup Current (Charge Pump)	ICHG_UP	During power-up VGATE_ = 1V	During power-up/power-down, VGATE_ = 1V		6		μΑ	
EN_OUT_ Pulldown Current (Charge Pump)	ICHG_DOWN	During power-up VGATE_ = 5V	p/power-down,		10		μΑ	
INPUTS (A0, GPIO_)								
Logic-Input Low Voltage	VIL					0.8	V	
Logic-Input High Voltage	VIH			2.0			V	
SMBus INTERFACE								
Logic-Input Low Voltage	VIL	Input voltage fall	ing			0.8	V	
Logic-Input High Voltage	VIH	Input voltage risi	ng	2.0			V	
Input Leakage Current		V <sub>CC</sub> shorted to G 3.3V	GND, SCL/SDA at 0V or	-1		+1	μΑ	
				-1		+1		
Output-Voltage Low	V <sub>OL</sub>	ISINK = 3mA				0.4	V	
Input Capacitance	C <sub>IN</sub>				5		pF	
SMBus TIMING	1	T		1			1	
Serial Clock Frequency	fscl					400	kHz	
Bus Free Time Between STOP	tBUF			1.3			μs	
START Condition Setup Time	tsu:sta			0.6			μs	
START Condition Hold Time	thd:STA			0.6			μs	
STOP Condition Setup Time	tsu:sto			0.6			μs	
Clock Low Period	tLOW			1.3			μs	
Clock High Period	<sup>t</sup> HIGH			0.6			μs	
Data Setup Time	tsu:dat			200			ns	
Output Fall Time	toF	10pF ≤ C <sub>BUS</sub> ≤ 400pF	$T_{A} = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $T_{A} = -40^{\circ}\text{C to } +125^{\circ}\text{C}$			250 500	ns	
		Receive	<u> </u>	0			İ	
Data Hold Time	thd:dat	Transmit		0.3		0.9	μs	
Pulse Width of Spike Suppressed	tsp				30		ns	

### **ELECTRICAL CHARACTERISTICS (continued)**

 $(V_{CC} = 3V \text{ to } 14V, T_A = -40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C}, \text{ unless otherwise specified. Typical values are at } V_{CC} = 3.3V, T_A = +25^{\circ}\text{C.})$  (Note 1)

JTAG INTERFACE         TDI, TMS, TCK Logic-Low Input Voltage $V_{IL}$ Input voltage falling         TDI, TMS, TCK Logic-High Input Voltage $V_{IH}$ Input voltage rising         TDO Logic-Output Low Voltage $V_{OL}$ TDO $V_{DBP} ≥ 2.5V$ , IsINK = 2mA         TDO Logic-Output High Voltage $V_{OH}$ TDO $V_{DBP} ≥ 2.5V$ , IsOURCE = 200μA         TDO Leakage Current       TDO high impedance         TDI, TMS Pullup Resistors       RJPU       Pullup to VDBP         Input/Output Capacitance $C_{I/O}$ JTAG TIMING         TCK Clock Period $t_1$ TCK High/Low Time $t_2$ , $t_3$	2 2.4 -1		0.55	V
Voltage   TDI, TMS, TCK Logic-High Input Voltage   TDO Logic-Output Low Voltage   TDO Logic-Output High Voltage   TDO Logic-Output High Voltage   TDO Leakage Current   TDO high impedance   TDI, TMS Pullup Resistors   TDI, TMS	2.4			
Voltage VIH Input Voltage TISING  TDO Logic-Output Low Voltage VOL_TDO VDBP $\geq$ 2.5V, ISINK = 2mA  TDO Logic-Output High Voltage VOH_TDO VDBP $\geq$ 2.5V, ISOURCE = 200 $\mu$ A  TDO Leakage Current TDO high impedance  TDI, TMS Pullup Resistors RJPU Pullup to VDBP  Input/Output Capacitance CI/O  JTAG TIMING  TCK Clock Period t1	2.4			٧
TDO Logic-Output High Voltage V <sub>OH_TDO</sub> V <sub>DBP</sub> ≥ 2.5V, I <sub>SOURCE</sub> = 200μA  TDO Leakage Current TDO high impedance  TDI, TMS Pullup Resistors R <sub>JPU</sub> Pullup to V <sub>DBP</sub> Input/Output Capacitance C <sub>I/O</sub> JTAG TIMING  TCK Clock Period t <sub>1</sub>			0.4	•
TDO Leakage Current TDO high impedance TDI, TMS Pullup Resistors RJPU Pullup to VDBP Input/Output Capacitance CI/O  JTAG TIMING TCK Clock Period  T DO high impedance Pullup to VDBP  TDO high impedance Pullup to VDBP  TDO high impedance TDO high impedance TDO high impedance TDO high impedance			0.4	V
TDI, TMS Pullup Resistors  RJPU Pullup to VDBP Input/Output Capacitance CI/O  JTAG TIMING  TCK Clock Period  t <sub>1</sub>	-1			V
Input/Output Capacitance CI/O  JTAG TIMING  TCK Clock Period t <sub>1</sub>			+1	μΑ
JTAG TIMING TCK Clock Period t <sub>1</sub>	7	10	13	kΩ
TCK Clock Period t <sub>1</sub>		5		рF
TCK High/Low Time to to			1000	ns
TOTAT III JULIUS TITLE	50	500		ns
TCK to TMS, TDI Setup Time t4	15			ns
TCK to TMS, TDI Hold Time t <sub>5</sub>	15			ns
TCK to TDO Delay t <sub>6</sub>			500	ns
TCK to TDO High-Z Delay t <sub>7</sub>			500	ns
EEPROM TIMING				
EEPROM Byte Write Cycle Time t <sub>WR</sub> (Note 6)		16	20	ms

- Note 1: Specifications are guaranteed for the stated global conditions, unless otherwise noted. 100% production tested at T<sub>A</sub> = +25°C and T<sub>A</sub> = +125°C. Specifications at T<sub>A</sub> = -40°C are guaranteed by design.
- Note 2: V<sub>UVLO</sub> is the minimum voltage on V<sub>CC</sub> to ensure the device is EEPROM configured.
- Note 3: Applies to RESET, fault, delay, and watchdog timeouts.
- Note 4: Total unadjusted error is a combination of gain, offset, and quantization error.
- Note 5: Guaranteed by design.
- **Note 6:** An additional cycle is required when writing to configuration memory for the first time.

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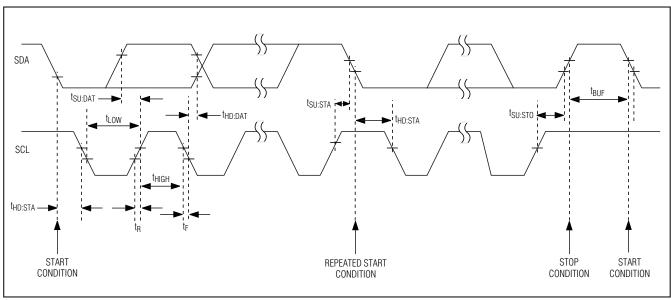


Figure 1. I<sup>2</sup>C/SMBus Timing Diagram

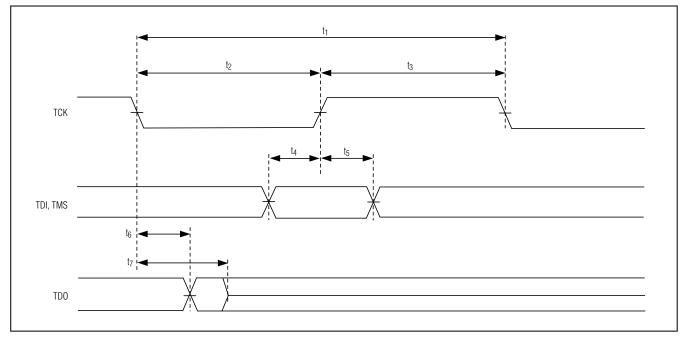
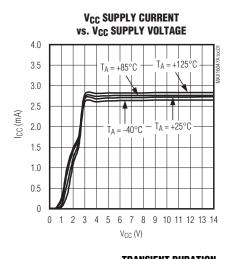
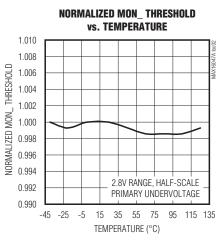


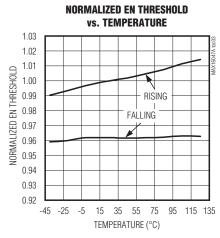
Figure 2. JTAG Timing Diagram

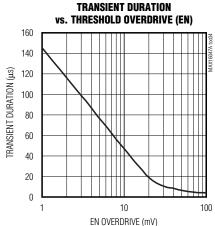
### **Typical Operating Characteristics**

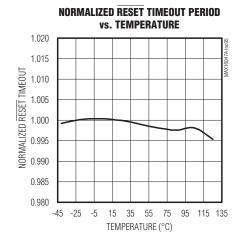
( $V_{CC} = 3.3V$ ,  $T_A = +25$ °C, unless otherwise noted.)

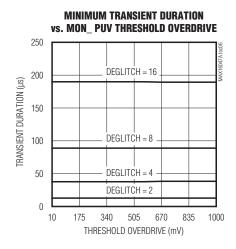


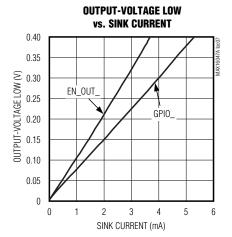






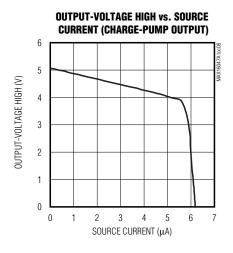


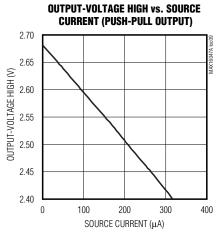


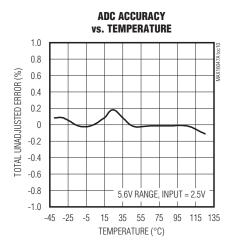


### Typical Operating Characteristics (continued)

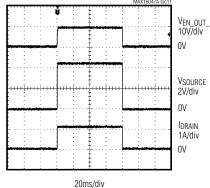
 $(V_{CC} = 3.3V, T_A = +25^{\circ}C, unless otherwise noted.)$ 

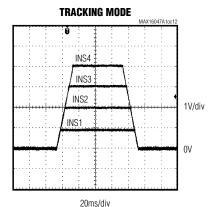




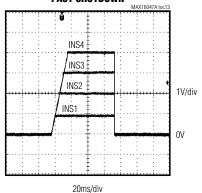




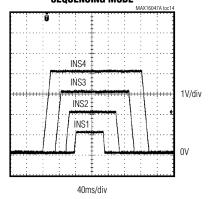




### TRACKING MODE WITH FAST SHUTDOWN

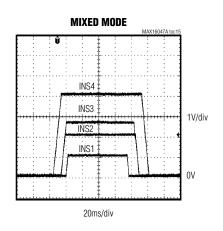


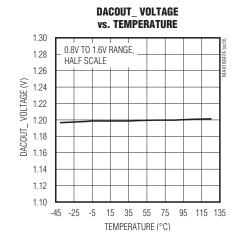
### SEQUENCING MODE

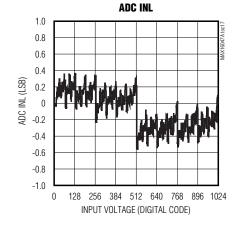


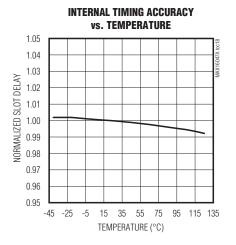
Typical Operating Characteristics (continued)

 $(V_{CC} = 3.3V, T_A = +25^{\circ}C, unless otherwise noted.)$ 









### **Pin Description**

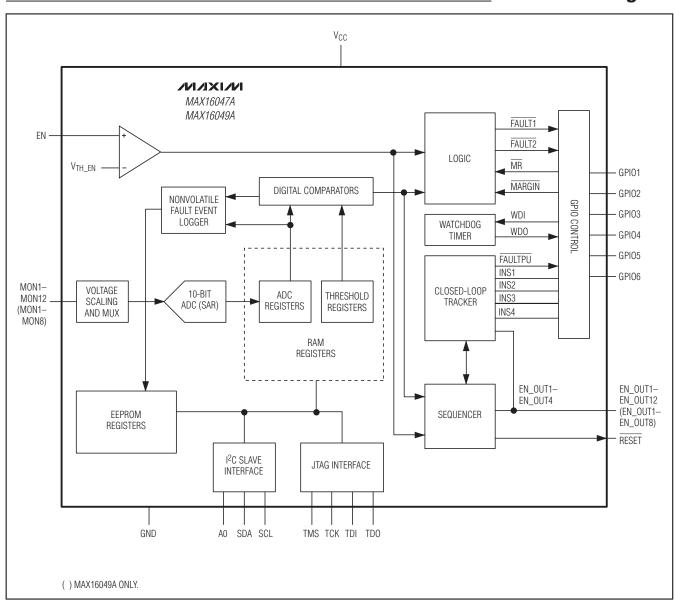
Р	PIN				
MAX16047A	MAX16049A	NAME	FUNCTION		
1–8	1–8	MON1-MO N8	ADC Monitored Voltage Inputs. Set ADC input range for each MON_ through configuration registers. Measured values are written to ADC registers and can be read back through the I <sup>2</sup> C or JTAG interface.		
9–12	_	MON9-MO N12	ADC Monitored Voltage Inputs. Set ADC input range through configuration registers. Measured values are written to ADC registers and can be read back through the I <sup>2</sup> C or JTAG interface.		
13	13	RESET	Configurable Reset Output		
14	14	A0	Four-State SMBus Address. Address sampled upon POR. Connect A0 to ground, DBP, SCL, or SDA to program an individual address when connecting multiple devices. See the <i>I</i> <sup>2</sup> <i>C/SMBus-Compatible Serial Interface</i> section.		
15	15	SCL	SMBus Serial Clock Input		
16	16	SDA	SMBus Serial Data Open-Drain Input/Output		
17	17	TMS	JTAG Test Mode Select		
18	18	TDI	JTAG Test Data In		
19	19	TCK	JTAG Test Clock		
20	20	TDO	JTAG Test Data Out		
21, 40	21, 40	GND	Ground. Connect all GND connections together.		
22	22	GPIO6	General-Purpose Input/Output. GPIO6 and GPIO5 are configurable as open-drain or push-pull outputs, dedicated fault outputs, or for watchdog functionality. GPIO5 is configurable as a watchdog input (WDI). GPIO6 is configurable as a watchdog output		
23	23	GPIO5	(WDO). GPIO6 is also configurable for margining. Use the EEPROM to configure GPIO5 and GPIO6. See the <i>General-Purpose Inputs/Outputs</i> section.		
24	24	EN	Analog Enable Input. Apply a voltage greater than the 0.525V (typ) threshold to enable all outputs. The power-down sequence is triggered when EN falls below 0.5V (typ) and all outputs are deasserted.		
25–36	9–12, 25–36, 53–56	N.C.	No Connection. Must be left unconnected.		

### Pin Description (continued)

PIN		NAME	FUNCTION
MAX16047A	MAX16049A	NAME	FUNCTION
37	37	ABP	Internal Analog Voltage Bypass. Bypass ABP to GND with a 1µF ceramic capacitor. ABP powers the internal circuitry of the MAX16047A/MAX16049A. Do not use ABP to power any external circuitry.
38	38	Vcc	Power-Supply Input. Bypass V <sub>CC</sub> to GND with a 10µF ceramic capacitor.
39	39	DBP	Internal Digital Voltage Bypass. Bypass DBP to GND with a 1µF ceramic capacitor. DBP supplies power to the EEPROM memory, to the internal logic circuitry, and to the internal charge pumps when the programmable outputs are configured as charge pumps. All push-pull outputs are referenced to DBP. Do not use DBP to power any external circuitry.
41	41	GPIO1	General-Purpose Input/Output 1. Configure GPIO1 as a logic input, a return sense line for closed-loop tracking, an open-drain/push-pull fault output, or an open-drain/push-pull output port. Use the EEPROM to configure GPIO1. See the <i>General-Purpose Inputs/Outputs</i> section.
42	42	GPIO2	General-Purpose Input/Output 2. GPIO2 is configurable as a logic input, a return sense line for closed-loop tracking, an open-drain/push-pull fault output, or an open-drain/push-pull output port. Use the EEPROM to configure GPIO2. See the <i>General-Purpose Inputs/Outputs</i> section.
43	43	GPIO3	General-Purpose Input/Output 3. GPIO3 is configurable as a logic input, a return sense line for closed-loop tracking, an open-drain/push-pull fault output, or an open-drain/push-pull output port. Use the EEPROM to configure GPIO3. See the <i>General-Purpose Inputs/Outputs</i> section.
44	44	GPIO4	General-Purpose Input/Output 4. GPIO4 is configurable as a logic input, a return sense line for closed-loop tracking, an open-drain/push-pull fault output, or an open-drain/push-pull output port. GPIO4 is also configurable as an active-low manual reset, $\overline{\text{MR}}$ . Use the EEPROM to configure GPIO4. See the <i>General-Purpose Inputs/Outputs</i> section.
45–50	45–50	EN_OUT1- EN_OUT6	Output. EN_OUT1-EN_OUT6 are configurable with active-high/active-low logic and with an open-drain or push-pull configuration. Program the EEPROM to configure EN_OUT1-EN_OUT6 as a charge-pump output 5V greater than the monitored input voltage (VMON_ + 5V). EN_OUT1-EN_OUT4 can also be used for closed-loop tracking.
51, 52	51, 52	EN_OUT7- EN_OUT8	Output. Configure EN_OUT_ with active-low/active-high logic and with an open-drain or push-pull configuration.
53–56	_	EN_OUT9- EN_OUT12	Output. Configure EN_OUT_ with active-low/active-high logic and with an open-drain or push-pull configuration.
_	_	EP	Exposed Pad. Internally connected to GND. Connect to GND. EP also functions as a heatsink to maximize thermal dissipation. Do not use as the main ground connection.

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### **Functional Diagram**



### Register Summary (All Registers 8-Bits Wide)

**Note:** This data sheet uses a specific convention for referring to bits within a particular address location. As an example, r0Fh[3:0] refers to bit 3 through 0 in register with address 15 decimal.

PAGE	REGISTER	DESCRIPTION
	ADC Conversion Results (Registers r00h to r17h)	Input ADC conversion results. ADC writes directly to these registers during normal operation. ADC input ranges (MON1–MON12) are selected with registers r0Fh to r11h.
Extended	Failed Line Flags (Registers r18h to r19h)	Voltage fault flag bits. Flags for each input signal when undervoltage or overvoltage threshold is exceeded.
	GPIO Data (Registers r1Ah to r1Bh)	GPIO state data. Used to read back and control the state of each GPIO.
	ADC Range Selections (Registers r0Fh to r11h)	ADC input voltage range. Selects the voltage range of the monitored inputs.
	Fault Behavior (Registers r47h to r4Ch)	Selects how the device should operate during faults. Options include latch-off or autoretry after fault. The autoretry delay is selectable (r4Fh). Use registers r48h through r4Ch to select fault conditions that trigger a critical fault event.
	GPIO Configuration (Registers r1Ch to r1Eh)	General-purpose input/output configuration registers. GPIOs are configurable as a manual-reset input, a margin disable input, a watchdog timer input and output, logic inputs/outputs, fault-dependent outputs, or as the feedback/pulldown inputs (INS_) for closed-loop tracking.
Default and EEPROM	Overvoltage and Undervoltage Thresholds (Registers r23h to r46h)	Input overvoltage and undervoltage thresholds. ADC conversion results are compared to overvoltage and undervoltage threshold values stored here. MON_ voltages exceeding threshold values trigger a fault event.
	Programmable Output Configuration (Registers r1Fh to r22h)	Programmable output configurations. Selectable output configurations include: active-low or active-high, open-drain or push-pull outputs. EN_OUT1-EN_OUT6 are configurable as charge-pump outputs, and EN_OUT1-EN_OUT4 can be configured for closed-loop tracking.
	RESET and Fault Outputs (Registers r15h to r1Bh)	RESET, FAULT1, and FAULT2 output configuration. Programs the functionality of the RESET, FAULT1, and FAULT2 outputs, as well as which inputs they depend on.
	Sequencing-Mode Configuration (Registers r50h to r5Bh and r5Eh to r63h)	Assign inputs and outputs for sequencing. Select sequence delays (20µs to 1.6s) with registers r50h through r54h. Use register r54h to enable/disable the reverse sequence bit for power-down operation.
	Software Enable and Margin (Register r4Dh)	Use register r4Dh to set the Software Enable bit, to select early warning thresholds and undervoltage/overvoltage, to enable/disable margining, and to enable/disable the watchdog for independent/dependent mode.
	Watchdog Functionality (Register r55h)	Configure watchdog functionality for GPIO5 and GPIO6.
EEPROM	Fault Log Results (Registers r00h to r0Eh)	ADC conversion results and failed-line flags at the time of a fault. These values are recorded by the fault event logger at the time of a critical fault.
LEFNOIVI	User EEPROM (Registers r9Ch to rFFh)	User-available EEPROM

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### **Detailed Description**

#### **Getting Started**

The MAX16047A is capable of managing up to twelve system voltages simultaneously, and the MAX16049A can manage up to eight system voltages. After bootup, if EN is high and the Software Enable bit is set to '0,' an internal multiplexer cycles through each input. At each multiplexer stop, the 10-bit ADC converts the monitored analog voltage to a digital result and stores the result in a register. Each time the multiplexer finishes a conversion (12.45µs max), internal logic circuitry compares the conversion results to the overvoltage and undervoltage thresholds stored in memory. If a conversion violates a programmed threshold, the conversion can be configured to generate a fault. Logic outputs can be programmed to depend on many combinations of faults. Additionally, faults are programmable to trigger the nonvolatile fault logger, which writes all fault information automatically to the EEPROM and write-protects the data to prevent accidental erasure.

The MAX16047A/MAX16049A contain both I<sup>2</sup>C/SMBuscompatible and JTAG serial interfaces for accessing registers and EEPROM. Use only one interface at any given time. For more information on how to access the internal memory through these interfaces, see the I<sup>2</sup>C/SMBusCompatible Serial Interface and JTAG Serial Interface sections. Registers are divided into three pages with access controlled by special I<sup>2</sup>C and JTAG commands.

The factory-default values at POR (power-on reset) for all RAM registers are '0's. POR occurs when V<sub>CC</sub> reaches the undervoltage-lockout threshold (UVLO) of 2.85V (max). At POR, the device begins a boot-up sequence. During the boot-up sequence, all monitored inputs are masked from initiating faults and EEPROM contents are copied to the respective register locations. During boot-up, the MAX16047A/MAX16049A are not accessible through the serial interface. The boot-up sequence can take up to 1.5ms, after which the device is ready for normal operation. RESET is low during boot-up and asserts after boot-up for its programmed timeout period once all monitored channels are within their respective thresholds. During boot-up, the GPIOs and EN\_OUTs are high impedance.

### Accessing the EEPROM

The MAX16047A/MAX16049A memory is divided into three separate pages. The default page, selected by default at POR, contains configuration bits for all functions of the part. The extended page contains the ADC conversion results and GPIO input and output registers. Finally, the EEPROM page contains all stored configuration information as well as saved fault data and user-defined data. See the *Register Map* table for more information on the function of each register.

During the boot-up sequence, the contents of the EEPROM (r0Fh to r7Dh) are copied into the default page (r0Fh to r7Dh). Registers r00h to r0Eh of the EEP-ROM page contain saved fault data.

The JTAG and I<sup>2</sup>C interfaces provide access to all three pages. Each interface provides commands to select and deselect a particular page:

- 98h(I<sup>2</sup>C)/09h(JTAG)—Switches to the extended page. Switch back to the default page with 99h(I<sup>2</sup>C)/0Ah(JTAG).
- 9Ah(I<sup>2</sup>C)/0Bh(JTAG)—Switches to the EEPROM page. Switch back to the default page with 9Bh(I<sup>2</sup>C)/0Ch(JTAG).

See the *I<sup>2</sup>C/SMBus-Compatible Serial Interface* or the *JTAG Serial Interface* section.

#### **Power**

Apply 3V to 14V to VCC to power the MAX16047A/MAX16049A. Bypass VCC to ground with a 10µF capacitor. Two internal voltage regulators, ABP and DBP, supply power to the analog and digital circuitry within the device. Do not use ABP or DBP to power external circuitry.

ABP is a 2.85V (typ) voltage regulator that powers the internal analog circuitry. Bypass the ABP output to GND with a  $1\mu$ F ceramic capacitor installed as close to the device as possible.

DBP is an internal 2.7V (typ) voltage regulator. EEPROM and digital circuitry are powered by DBP. All push-pull outputs are referenced to DBP. DBP supplies the input voltage to the internal charge pumps when the programmable outputs are configured as charge-pump outputs. Bypass the DBP output to GND with a 1µF ceramic capacitor installed as close as possible to the device.

Table 1. EEPROM Software Enable Configurations

REGISTER/ EEPROM ADDRESS	BIT RANGE	DESCRIPTION
4Dh	0	Software Enable bit 0 = Enabled. EN must also be high to begin sequencing 1 = Disabled (factory default)
	1	Margin bit 1 = Margin functionality is enabled 0 = Margin disabled
	2	Early Warning Selection bit  0 = Early warning thresholds are undervoltage thresholds  1 = Early warning thresholds are overvoltage thresholds
	3	Watchdog Mode Selection bit 0 = Watchdog timer is in dependent mode 1 = Watchdog timer is in independent mode
	[7:4]	Not used

#### **Enable**

To initiate sequencing/tracking and enable monitoring, the voltage at EN must be above 0.525V and the Software Enable bit in r4Dh[0] must be set to '0.' To power down and disable monitoring, either pull EN below 0.5V or set the Software Enable bit to '1.' See Table 1 for the software enable bit configurations. Connect EN to ABP if not used.

If a fault condition occurs during the power-up cycle, the EN\_OUT\_ outputs are powered down immediately, independent of the state of EN. If operating in latch-on fault mode, toggle EN or toggle the Software Enable bit to clear the latch condition and restart the device once the fault condition has been removed. If EN is driven by external logic instead of from the center tap of a VCC-connected resistive divider, ensure that an active-high pulse occurs on EN within 1.5ms of VCC exceeding 2.85V. If the external driving logic is in the high-impedance state during power-up, this pulse can be created by connecting an external pullup resistor to EN.

#### Voltage Monitoring

The MAX16047A/MAX16049A feature an internal 10-bit ADC that monitors the MON\_ voltage inputs. An internal multiplexer cycles through each of the twelve inputs, taking 150µs (typ) for a complete monitoring cycle. Each acquisition takes approximately 12.45µs. At each multiplexer stop, the 10-bit ADC converts the analog input to a digital result and stores the result in a regis-

ter. ADC conversion results are stored in registers r00h to r17h in the extended page. Use the I<sup>2</sup>C or JTAG serial interface to read ADC conversion results. See the I<sup>2</sup>C/SMBus-Compatible Serial Interface or the JTAG Serial Interface section for more information on accessing the extended page.

The MAX16047A provides twelve inputs, MON1–MON12, for voltage monitoring. The MAX16049A provides eight inputs, MON1–MON8, for voltage monitoring. Each input voltage range is programmable in registers r0Fh to r11h (see Table 2). When MON\_ configuration registers are set to '11,' MON\_ voltages are not monitored or converted, and the multiplexer does not stop at these inputs, decreasing the total cycle time. These inputs cannot be configured to trigger fault conditions.

The three programmable thresholds for each monitored voltage include an overvoltage, an undervoltage, and an early warning threshold that can be set in r4Dh[2] to be either an undervoltage or overvoltage threshold. See the *Faults* section for more information on setting overvoltage and undervoltage thresholds. All voltage thresholds are 8 bits wide. The 8 MSBs of the 10-bit ADC conversion result are compared to these overvoltage and undervoltage thresholds.

For any undervoltage or overvoltage condition to be monitored and any faults detected, the MON\_ input must be assigned to a particular sequence order. See the *Sequencing* section for more details on assigning MON\_ inputs.

**Table 2. Input Monitor Ranges and Enables** 

REGISTER/ EEPROM ADDRESS	BIT RANGE	DESCRIPTION
	[1:0]	MON1 Voltage Range Selection:  00 = From 0 to 5.6V in 5.46mV steps  01 = From 0 to 2.8V in 2.73mV steps  10 = From 0 to 1.4V in 1.36mV steps  11 = MON1 is not converted or monitored
0Fh	[3:2]	MON2 Voltage Range Selection:  00 = From 0 to 5.6V in 5.46mV steps  01 = From 0 to 2.8V in 2.73mV steps  10 = From 0 to 1.4V in 1.36mV steps  11 = MON2 is not converted or monitored
OI II	[5:4]	MON3 Voltage Range Selection:  00 = From 0 to 5.6V in 5.46mV steps  01 = From 0 to 2.8V in 2.73mV steps  10 = From 0 to 1.4V in 1.36mV steps  11 = MON3 is not converted or monitored
	[7:6]	MON4 Voltage Range Selection:  00 = From 0 to 5.6V in 5.46mV steps  01 = From 0 to 2.8V in 2.73mV steps  10 = From 0 to 1.4V in 1.36mV steps  11 = MON4 is not converted or monitored
	[1:0]	MON5 Voltage Range Selection:  00 = From 0 to 5.6V in 5.46mV steps  01 = From 0 to 2.8V in 2.73mV steps  10 = From 0 to 1.4V in 1.36mV steps  11 = MON5 is not converted or monitored
101	[3:2]	MON6 Voltage Range Selection:  00 = From 0 to 5.6V in 5.46mV steps  01 = From 0 to 2.8V in 2.73mV steps  10 = From 0 to 1.4V in 1.36mV steps  11 = MON6 is not converted or monitored
10h	[5:4]	MON7 Voltage Range Selection:  00 = From 0 to 5.6V in 5.46mV steps  01 = From 0 to 2.8V in 2.73mV steps  10 = From 0 to 1.4V in 1.36mV steps  11 = MON7 is not converted or monitored
	[7:6]	MON8 Voltage Range Selection:  00 = From 0 to 5.6V in 5.46mV steps  01 = From 0 to 2.8V in 2.73mV steps  10 = From 0 to 1.4V in 1.36mV steps  11 = MON8 is not converted or monitored

**Table 2. Input Monitor Ranges and Enables (continued)** 

REGISTER/ EEPROM ADDRESS	BIT RANGE	DESCRIPTION
	[1:0]	MON9 Voltage Range Selection*:  00 = From 0 to 5.6V in 5.46mV steps  01 = From 0 to 2.8V in 2.73mV steps  10 = From 0 to 1.4V in 1.36mV steps  11 = MON9 is not converted or monitored
	[3:2]	MON10 Voltage Range Selection*:  00 = From 0 to 5.6V in 5.46mV steps  01 = From 0 to 2.8V in 2.73mV steps  10 = From 0 to 1.4V in 1.36mV steps  11 = MON10 is not converted or monitored
11h	[5:4]	MON11 Voltage Range Selection*:  00 = From 0 to 5.6V in 5.46mV steps  01 = From 0 to 2.8V in 2.73mV steps  10 = From 0 to 1.4V in 1.36mV steps  11 = MON11 is not converted or monitored
	[7:6]	MON12 Voltage Range Selection*: 00 = From 0 to 5.6V in 5.46mV steps 01 = From 0 to 2.8V in 2.73mV steps 10 = From 0 to 1.4V in 1.36mV steps 11 = MON12 is not converted or monitored

<sup>\*</sup>MAX16047A only

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The extended memory page contains the ADC conversion result registers (see Table 3). These registers are also used internally for fault threshold comparison. Voltage-monitoring thresholds are compared with the 8 MSBs of the conversion results. Inputs that are not

enabled are not converted by the ADC; they contain the last value acquired before that channel was disabled.

The ADC conversion result registers are reset to 00h at boot-up. These registers are not reset when a reboot command is executed.

**Table 3. ADC Conversion Registers** 

EXTENDED PAGE ADDRESS	BIT RANGE	DESCRIPTION
00h	[7:0]	MON1 ADC Conversion Result (MSB)
041	[7:6]	MON1 ADC Conversion Result (LSB)
01h	[5:0]	Reserved
02h	[7:0]	MON2 ADC Conversion Result (MSB)
001-	[7:6]	MON2 ADC Conversion Result (LSB)
03h	[5:0]	Reserved
04h	[7:0]	MON3 ADC Conversion Result (MSB)
OCh	[7:6]	MON3 ADC Conversion Result (LSB)
05h	[5:0]	Reserved
06h	[7:0]	MON4 ADC Conversion Result (MSB)
07h	[7:6]	MON4 ADC Conversion Result (LSB)
U/II	[5:0]	Reserved
08h	[7:0]	MON5 ADC Conversion Result (MSB)
09h	[7:6]	MON5 ADC Conversion Result (LSB)
0911	[5:0]	Reserved
0Ah	[7:0]	MON6 ADC Conversion Result (MSB)
0Bh	[7:6]	MON6 ADC Conversion Result (LSB)
UDII	[5:0]	Reserved
0Ch	[7:0]	MON7 ADC Conversion Result (MSB)
0Dh	[7:6]	MON7 ADC Conversion Result (LSB)
UDII	[5:0]	Reserved
0Eh	[7:0]	MON8 ADC Conversion Result (MSB)
0Fh	[7:6]	MON8 ADC Conversion Result (LSB)
UFII	[5:0]	Reserved
10h	[7:0]	MON9 ADC Conversion Result (MSB)*
11h	[7:6]	MON9 ADC Conversion Result (LSB)*
1 111	[5:0]	Reserved
12h	[7:0]	MON10 ADC Conversion Result (MSB)*
12h	[7:6]	MON10 ADC Conversion Result (LSB)*
13h	[5:0]	Reserved
14h	[7:0]	MON11 ADC Conversion Result (MSB)*
15h	[7:6]	MON11 ADC Conversion Result (LSB)*
	[5:0]	Reserved
16h	[7:0]	MON12 ADC Conversion Result (MSB)*
17h	[7:6]	MON12 ADC Conversion Result (LSB)*
1/11	[5:0]	Reserved

<sup>\*</sup>MAX16047A only

#### **General-Purpose Inputs/Outputs**

GPIO1-GPIO6 are programmable general-purpose inputs/outputs. GPIO1-GPIO6 are configurable as a manual reset input, a margin disable input, a watchdog timer input and output, logic inputs/outputs, fault-

dependent outputs, or as the feedback inputs (INS\_) for closed-loop tracking. When programmed as outputs, GPIOs are open drain or push-pull. See registers r1Ch to r1Eh in Tables 4 and 5 for more detailed information on configuring GPIO1–GPIO6.

Table 4. General-Purpose IO Configuration Registers

REGISTER/ EEPROM ADDRESS	BIT RANGE	DESCRIPTION
	[2:0]	GPIO1 Configuration Register
1Ch	[5:3]	GPIO2 Configuration Register
	[7:6]	GPIO3 Configuration Register (LSB)
	[0]	GPIO3 Configuration Register (MSB)
1Dh	[3:1]	GPIO4 Configuration Register
וטח	[6:4]	GPIO5 Configuration Register
	[7]	GPIO6 Configuration Register (LSB)
1Eh	[1:0]	GPIO6 Configuration Register (MSB)
	[7:2]	Reserved

### **Table 5. GPIO Mode Selection**

CONFIGURATION BITS	GPIO1	GPIO2	GPIO3	GPIO4	GPIO5	GPIO6
000	INS1	INS2	INS3	INS4		MARGIN input
001	Push-pull logic input/output	Push-pull logic input/output				
010	Open-drain logic input/output	Open-drain logic input/output	Open-drain logic input/output	Open-drain logic input/output	Open-drain logic input/ output	Open-drain logic input/ output
011	Push-pull Any_Fault output	Push-pull Any_Fault output	Push-pull Any_Fault output	Push-pull Any_Fault output	Push-pull FAULT1 output	Push-pull FAULT2 output
100	Open-drain Any_Fault output	Open-drain Any_Fault output	Open-drain Any_Fault output	Open-drain Any_Fault output	Open-drain FAULT1 output	Open-drain FAULT2 output
101	Logic input	Logic input				
110	_	_	_	_	_	Open-drain WDO output
111	_	_	_	MR input	WDI input	Open-drain FAULTPU output

Note: The dash "—" represents a reserved GPIO configuration. Do not set any GPIO to these values.

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#### Voltage Tracking Sense (INS ) Inputs

GPIO1-GPIO4 are configurable as feedback sense return inputs (INS\_) for closed-loop tracking. Connect the gate of an external n-channel MOSFET to each EN\_OUT\_ configured for closed-loop tracking. Connect INS\_ inputs to the source of the MOSFETs for tracking feedback.

Internal comparators monitor INS\_ with respect to a control tracking ramp voltage for power-up/power-down and control each EN\_OUT\_ voltage. Under normal conditions each INS\_ voltage tracks the ramp voltage until the power-good voltage threshold has been reached. The slew rate for the ramp voltage and the INS\_ to MON\_ power-good threshold are programmable. See the *Closed-Loop Tracking* section.

INS\_ connections also act as  $100\Omega$  pulldowns for closed-loop tracking channels or for other power supplies, if INS\_ are connected to the outputs of the supplies. Set the appropriate bits in r4Eh[7:4] to enable pulldown functionality. See Table 12.

### General-Purpose Logic Inputs/Outputs

Configure GPIO1–GPIO6 to be used as general-purpose inputs/outputs. Write values to GPIOs through r1Ah when operating as outputs, and read values from r1Bh when operating as inputs. Register r1Bh is readonly. See Table 6 for more information on reading and writing to the GPIOs as logic inputs/outputs. Both registers r1Ah and r1Bh are located in the extended page and are therefore not loaded from EEPROM on boot-up.

Table 6. GPIO Data-In/Data-Out Data

EXTENDED PAGE ADDRESS	BIT RANGE	DESCRIPTION
	[0]	GPIO Logic Output Data 0 = GPIO1 is a logic-low output 1 = GPIO1 is a logic-high output
	[1]	0 = GPIO2 is a logic-low output 1 = GPIO2 is a logic-high output
1Ah	[2]	0 = GPIO3 is a logic-low output 1 = GPIO3 is a logic-high output
TAIT	[3]	0 = GPIO4 is a logic-low output 1 = GPIO4 is a logic-high output
	[4]	0 = GPIO5 is a logic-low output 1 = GPIO5 is a logic-high output
	[5]	0 = GPIO6 is a logic-low output 1 = GPIO6 is a logic-high output
	[7:6]	Not used
	[0]	GPIO Logic Input Data GPIO1 logic-input state
	[1]	GPIO2 logic-input state
1Bh	[2]	GPIO3 logic-input state
IDII	[3]	GPIO4 logic-input state
	[4]	GPIO5 logic-input state
	[5]	GPIO6 logic-input state
	[7:6]	Not used

### Any\_Fault Outputs

GPIO1–GPIO4 are configurable as active-low push-pull or open-drain fault-dependent outputs. These outputs assert when any monitored input exceeds an overvoltage, undervoltage, or early warning threshold.

### FAULT1 and FAULT2

GPIO5 and GPIO6 are configurable as dedicated fault outputs, FAULT1 and FAULT2, respectively. Fault

outputs can assert on one or more overvoltage, undervoltage, or early warning conditions for selected inputs. FAULT1 and FAULT2 dependencies are set using registers r15h to r18h. See Table 7.

If a fault output depends on more than one MON\_, the fault output will assert if one or more MON\_ exceeds a programmed threshold voltage.

Table 7. FAULT1 and FAULT2 Output Configuration and Dependencies

REGISTER/ EEPROM ADDRESS	BIT RANGE	DESCRIPTION
	[0]	1 = FAULT1 is a digital output dependent on MON1
	[1]	1 = FAULT1 is a digital output dependent on MON2
	[2]	1 = FAULT1 is a digital output dependent on MON3
15h	[3]	1 = FAULT1 is a digital output dependent on MON4
150	[4]	1 = FAULT1 is a digital output dependent on MON5
	[5]	1 = FAULT1 is a digital output dependent on MON6
	[6]	1 = FAULT1 is a digital output dependent on MON7
	[7]	1 = FAULT1 is a digital output dependent on MON8
	[0]	1 = FAULT1 is a digital output dependent on MON9*
	[1]	1 = FAULT1 is a digital output dependent on MON10*
	[2]	1 = FAULT1 is a digital output dependent on MON11*
	[3]	1 = FAULT1 is a digital output dependent on MON12*
16h	[4]	$1 = \overline{FAULT1}$ is a digital output that depends on the overvoltage thresholds at the input selected by r15h and r16h[3:0]
1011	[5]	1 = FAULT1 is a digital output that depends on the undervoltage thresholds at the input selected by r15h and r16h[3:0]
	[6]	1 = FAULT1 is a digital output that depends on the early warning thresholds at the input selected by r15h and r16h[3:0]
	[7]	0 = FAULT1 is an active-low digital output 1 = FAULT1 is an active-high digital output
	[0]	1 = FAULT2 is a digital output dependent on MON1
	[1]	1 = FAULT2 is a digital output dependent on MON2
	[2]	1 = FAULT2 is a digital output dependent on MON3
17h	[3]	1 = FAULT2 is a digital output dependent on MON4
1/11	[4]	1 = FAULT2 is a digital output dependent on MON5
	[5]	1 = FAULT2 is a digital output dependent on MON6
	[6]	1 = FAULT2 is a digital output dependent on MON7
	[7]	1 = FAULT2 is a digital output dependent on MON8

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Table 7. FAULT1 and FAULT2 Output Configuration and Dependencies (continued)

REGISTER/ EEPROM ADDRESS	BIT RANGE	DESCRIPTION
	[0]	1 = FAULT2 is a digital output dependent on MON9*
	[1]	1 = FAULT2 is a digital output dependent on MON10*
	[2]	1 = FAULT2 is a digital output dependent on MON11*
	[3]	1 = FAULT2 is a digital output dependent on MON12*
18h	[4]	$1 = \overline{FAULT2}$ is a digital output that depends on the overvoltage thresholds at the input selected by r17h and r18h[3:0]
1011	[5]	$1 = \overline{FAULT2}$ is a digital output that depends on the undervoltage thresholds at the input selected by r17h and 18h[3:0]
	[6]	$1 = \overline{FAULT2}$ is a digital output that depends on the early warning thresholds at the input selected by r17h and r18h[3:0]
	[7]	0 = FAULT2 is an active-low digital output 1 = FAULT2 is an active-high digital output

<sup>\*</sup>MAX16047A only

#### Fault-On Power-Up (FAULTPU)

GPIO6 indicates a fault during power-up or power-down when configured as a "fault-on power-up" output. Under these conditions, all EN\_OUT\_ voltages are pulled low and fault data is saved to nonvolatile EEPROM. See the *Faults* section.

### MARGIN

GPIO6 is configurable as an active-low  $\overline{\text{MARGIN}}$  input. Drive  $\overline{\text{MARGIN}}$  low before varying system voltages above or below the thresholds to avoid signaling an error. Drive  $\overline{\text{MARGIN}}$  high for normal operation.

When MARGIN is pulled low or r4Dh[1] is a '1,' the margin function is enabled. FAULT1, FAULT2, Any\_Fault, and RESET are latched in their current state. Threshold violations will be ignored, and faults will not be logged.

#### Manual Reset (MR)

GPIO4 is configurable to act as an active-low manual reset input, MR. Drive MR low to assert RESET. RESET remains low for the selected reset timeout period after MR transitions from low to high. See the RESET section for more information on selecting a reset timeout period.

### Watchdog Input (WDI) and Output (WDO)

Set r1Eh[1:0] and r1Dh[7] to '110' to configure GPIO6 as WDO. Set r1Dh[6:4] to '111' to configure GPIO5 as WDI. WDO is an open-drain active-low output. See the *Watchdog Timer* section for more information about the operation of the watchdog timer.

### Programmable Outputs (EN\_OUT1-EN\_OUT12)

The MAX16047A includes twelve programmable outputs, and the MAX16049A includes eight programmable outputs. These outputs are capable of connecting to either the enable (EN) inputs of a DC-DC or LDO power supply or to the gates of series-pass MOSFETs for closed-loop tracking mode, or for charge-pump mode. Selectable output configurations include: active-low or active-high, open-drain or push-pull. EN\_OUT1-EN\_OUT4 are also configurable for closed-loop tracking, and EN\_OUT1-EN\_OUT6 can act as charge-pump outputs with no closed-loop tracking. Use the registers r1Fh to r22h to configure outputs. See Table 8 for detailed information on configuring EN\_OUT1-EN\_OUT12.

### Table 8. EN\_OUT1-EN\_OUT12 Configuration

REGISTER/ EEPROM ADDRESS	BIT RANGE	DESCRIPTION
	[2:0]	EN_OUT1 Configuration:  000 = EN_OUT1 is an open-drain active-low output  001 = EN_OUT1 is an open-drain active-high output  010 = EN_OUT1 is a push-pull active-low output  011 = EN_OUT1 is a push-pull active-high output  100 = EN_OUT1 is used in closed-loop tracking  101 = EN_OUT1 is configured with a charge-pump output (MON1 + 5V) capable of driving an external n-channel MOSFET  110 = Reserved
1Fh	[5:3]	EN_OUT2 Configuration:  000 = EN_OUT2 is an open-drain active-low output  001 = EN_OUT2 is an open-drain active-high output  010 = EN_OUT2 is a push-pull active-low output  011 = EN_OUT2 is a push-pull active-high output  100 = EN_OUT2 is used in closed-loop tracking  101 = EN_OUT2 is configured with a charge-pump output (MON2 + 5V) capable of driving an external n-channel MOSFET  110 = Reserved
	[7:6]	EN_OUT3 Configuration (LSBs):  000 = EN_OUT3 is an open-drain active-low output  001 = EN_OUT3 is an open-drain active-high output  010 = EN_OUT3 is a push-pull active-low output  011 = EN_OUT3 is a push-pull active-high output  100 = EN_OUT3 is used in closed-loop tracking  101 = EN_OUT3 is configured with a charge-pump output (MON3 + 5V) capable of driving an external n-channel MOSFET  110 = Reserved

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Table 8. EN\_OUT1-EN\_OUT12 Configuration (continued)

REGISTER/ EEPROM ADDRESS	BIT RANGE	DESCRIPTION
	[0]	EN_OUT3 Configuration (MSB)—see r1Fh[7:6]
20h	[3:1]	EN_OUT4 Configuration:  000 = EN_OUT4 is an open-drain active-low output  001 = EN_OUT4 is an open-drain active-high output  010 = EN_OUT4 is a push-pull active-low output  011 = EN_OUT4 is a push-pull active-high output  100 = EN_OUT4 is used in closed-loop tracking  101 = EN_OUT4 is configured with a charge-pump output (MON4 + 5V) capable of driving an external n-channel MOSFET  110 = Reserved  111 = Reserved
	[6:4]	EN_OUT5 Configuration:  000 = EN_OUT5 is an open-drain active-low output  001 = EN_OUT5 is an open-drain active-high output  010 = EN_OUT5 is a push-pull active low output  011 = EN_OUT5 is a push-pull active-high output  100 = Reserved. EN_OUT5 is not usable for closed-loop tracking.  101 = EN_OUT5 is configured with a charge-pump output (MON5 + 5V) capable of driving an external n-channel MOSFET  110 = Reserved  111 = Reserved
	[7]	EN_OUT6 Configuration (LSB)—see r21h[1:0]
	[1:0]	EN_OUT6 Configuration (MSBs):  000 = EN_OUT6 is an open-drain active-low output  001 = EN_OUT6 is an open-drain active-high output  010 = EN_OUT6 is a push-pull active-low output  011 = EN_OUT6 is a push-pull active-high output  100 = Reserved. EN_OUT6 is not useable for closed-loop tracking.  101 = EN_OUT6 is configured with a charge-pump output (MON6 + 5V) capable of driving an external n-channel MOSFET  110 = Reserved  111 = Reserved
21h	[3:2]	EN_OUT7 Configuration:  00 = EN_OUT7 is an open-drain active-low output  01 = EN_OUT7 is an open-drain active-high output  10 = EN_OUT7 is a push-pull active-low output  11 = EN_OUT7 is a push-pull active-high output
	[5:4]	EN_OUT8 Configuration:  00 = EN_OUT8 is an open-drain active-low output  01 = EN_OUT8 is an open-drain active-high output  10 = EN_OUT8 is a push-pull active-low output  11 = EN_OUT8 is a push-pull active-high output
	[7:6]	EN_OUT9 Configuration*:  00 = EN_OUT9 is an open-drain active-low output  01 = EN_OUT9 is an open-drain active-high output  10 = EN_OUT9 is a push-pull active-low output  11 = EN_OUT9 is a push-pull active-high output

Table 8. EN\_OUT1-EN\_OUT12 Configuration (continued)

REGISTER/ EEPROM ADDRESS	BIT RANGE	DESCRIPTION
	[1:0]	EN_OUT10 Configuration*:  00 = EN_OUT10 is an open-drain active-low output  01 = EN_OUT10 is an open-drain active-high output  10 = EN_OUT10 is a push-pull active-low output  11 = EN_OUT10 is a push-pull active-high output
22h	[3:2]	EN_OUT11 Configuration*:  00 = EN_OUT11 is an open-drain active-low output  01 = EN_OUT11 is an open-drain active-high output  10 = EN_OUT11 is a push-pull active-low output  11 = EN_OUT11 is a push-pull active-high output
	[5:4]	EN_OUT12 Configuration*:  00 = EN_OUT12 is an open-drain active-low output  01 = EN_OUT12 is an open-drain active high output  10 = EN_OUT12 is a push-pull active-low output  11 = EN_OUT12 is a push-pull active-high output
	[7:6]	Reserved

<sup>\*</sup>MAX16047A only

#### Charge-Pump Configuration

EN\_OUT1-EN\_OUT6 can act as high-voltage charge-pump outputs to drive up to six external n-channel MOSFETs. During sequencing, an EN\_OUT\_ output configured this way drives 6µA until the voltage reaches 5V above the corresponding MON\_ to fully enhance the external n-channel MOSFET. For example, EN\_OUT2 will rise to 5V above MON2. See the Sequencing section for more detailed information on power-supply sequencing.

#### Closed-Loop Tracking Operation

EN\_OUT1-EN\_OUT4 can operate in closed-loop tracking mode. When configured for closed-loop tracking, EN\_OUT1-EN\_OUT4 are capable of driving the gates of up to four external n-channel MOSFETs. For closed-loop tracking, configure GPIO1-GPIO4 as return-sense line inputs (INS\_) to be used in conjunction with EN\_OUT1-EN\_OUT4 and MON1-MON4. See the Closed-Loop Tracking section.

#### Open-Drain Output Configuration

Connect an external pullup resistor from the output to an external voltage up to 6V (abs max, EN\_OUT7-EN\_OUT12) or 12V (abs max, EN\_OUT1-EN\_OUT6) when configured as an open-drain output. Choose the pullup resistor depending on the number of devices connected to the open-drain output and the allowable current consumption. The open-drain output configuration allows wire-ORed connection.

#### Push-Pull Output Configuration

The MAX16047A/MAX16049As' programmable outputs sink 2mA and source 100µA when configured as push-pull outputs.

### EN\_OUT\_ State During Power-Up

When VCC is ramped from 0V to the operating supply voltage, the EN\_OUT\_ output is high impedance until VCC is approximately 2.4V and then EN\_OUT\_ will be in its configured deasserted state. See Figures 3 and 4. RESET is configured as an active-low open-drain output pulled up to VCC through a  $10k\Omega$  resistor for Figures 3 and 4.

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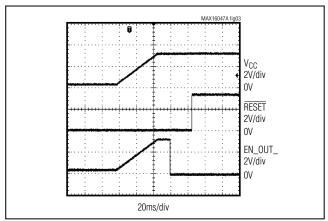


Figure 3. RESET and EN\_OUT\_ During Power-Up, EN\_OUT\_ Is in Open-Drain Active-Low Configuration

### Sequencing

Each EN\_OUT\_ has one or more associated MON\_ inputs, facilitating the voltage monitoring of multiple power supplies. To sequence a system of power supplies safely, the output voltage of a power supply must be good before the next power supply may turn on. Connect EN\_OUT\_ outputs to the enable input of an external power supply and connect MON\_ inputs to the output of the power supply for voltage monitoring. More than one MON\_ may be used if the power supply has multiple outputs.

#### Sequence Order

The MAX16047A/MAX16049A utilize a system of ordered slots to sequence multiple power supplies. To determine the sequence order, assign each EN\_OUT\_ to a slot ranging from Slot 0 to Slot 11. EN\_OUT\_(s) assigned to Slot 0 are turned on first, followed by outputs assigned to Slot 1, and so on through Slot 11. Multiple EN\_OUT\_s assigned to the same slot turn on at the same time.

Each slot has a built-in configurable sequence delay (registers r50h to r54h) ranging from 20µs to 2.4s. During a reverse sequence, slots are turned off in reverse order starting from Slot 11. The MAX16047A/MAX16049A may be configured to power-down in simultaneous mode or in reverse sequence mode as set in r54h[4]. See Tables 9, 10, and 11 for the EN\_OUT\_ slot assignment bits and Tables 12 and 13 for the sequence delays.

#### Monitoring Inputs While Sequencing

An enabled MON\_ input may be assigned to a slot ranging from Slot 1 to Slot 12. Monitoring inputs are always checked at the beginning of a slot. The inputs are given the power-up fault delay within which they must satisfy the programmed undervoltage limit; otherwise a fault

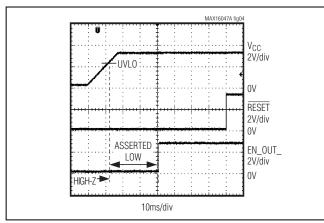


Figure 4. RESET and EN\_OUT\_ During Power-Up, EN\_OUT\_ Is in Push-Pull Active-High Configuration

condition will occur. The fault occurs regardless of the critical fault enable bits. This undervoltage limit cannot be disabled during power-up and power-down. EN\_OUT\_s configured for open-drain, push-pull, or charge-pump operation are always asserted at the end of a slot, following the sequence delay. See Tables 9, 10, and 11 for the MON\_ slot assignment bits.

Slot 0 does <u>not monitor any MON\_</u> input. Instead, Slot 0 waits for the Software Enable bit r4Dh[0] to be a logic '0' and for the voltage on EN to rise above 0.525V before asserting any assigned outputs. Outputs assigned to Slot 0 are asserted before the Slot 0 sequence delay. Generally, Slot 0 controls the enable inputs of power supplies that are first in the sequence.

Similarly, Slot 12 does not control any EN\_OUT\_ outputs. Rather, Slot 12 monitors assigned MON\_ inputs and then enters the power-on state. Generally, Slot 12 monitors the last power supplies in the sequence. The power-up sequence is complete when any MON\_ inputs assigned to Slot 12 exceed their undervoltage thresholds and the sequence delay is expired. If no MON\_ inputs are assigned to Slot 12, the power-up sequence is complete after the slot sequence delay is expired.

The output rail(s) of a power supply should be monitored by one or more MON\_ inputs placed in the succeeding slot, ensuring that the output of the supply is not checked until it has first been turned on. For example, if a power supply uses EN\_OUT1 located in Slot 3 and has two monitoring inputs, MON1 and MON2, they must both be assigned to Slot 4. In this example, EN\_OUT1 turns on at the end of Slot 3. At the start of Slot 4, MON1 and MON2 must exceed the undervoltage threshold before the programmed power-up fault delay; otherwise a fault triggers.

#### RESET Deassertion

After any MON\_ inputs assigned to Slot 12 exceed their undervoltage thresholds, the reset timeout begins. When the reset timeout completes, RESET deasserts. The reset timeout period is set in r19h[6:4]. See Table 21.

#### Power-Down

Power-down starts when EN is pulled low or the Software Enable bit is set to '1.' RESET asserts as soon as power-down begins regardless of the reset output

dependencies. Power down EN\_OUT\_s simultaneously or in reverse sequence mode by setting the Reverse Sequence bit (r54h[4]) appropriately. In reverse sequence mode (r54h[4] set to '1'), the EN\_OUT\_s assigned to Slot 11 deassert, the MAX16047A/MAX16049A wait for the Slot 11 sequence delay and then proceed to Slot 10, and so on until the EN\_OUT\_s assigned to Slot 0 turn off. When simultaneous powerdown is selected (r54h[4] set to '0'), all EN\_OUT\_s turn off at the same time.

Table 9. MON\_ and EN\_OUT\_ Slot Assignment Registers

REGISTER/ EEPROM ADDRESS	BIT RANGE	DESCRIPTION
r Ch	[3:0]	MON1 Slot Assignment Register
56h	[7:4]	MON2 Slot Assignment Register
57h	[3:0]	MON3 Slot Assignment Register
5711	[7:4]	MON4 Slot Assignment Register
58h	[3:0]	MON5 Slot Assignment Register
3611	[7:4]	MON6 Slot Assignment Register
59h	[3:0]	MON7 Slot Assignment Register
3911	[7:4]	MON8 Slot Assignment Register
5Ah	[3:0]	MON9 Slot Assignment Register*
DAII	[7:4]	MON10 Slot Assignment Register*
5Bh	[3:0]	MON11 Slot Assignment Register*
JDII	[7:4]	MON12 Slot Assignment Register*
5Eh	[3:0]	EN_OUT1 Slot Assignment Register
SEII	[7:4]	EN_OUT2 Slot Assignment Register
5Fh	[3:0]	EN_OUT3 Slot Assignment Register
SEII	[7:4]	EN_OUT4 Slot Assignment Register
60h	[3:0]	EN_OUT5 Slot Assignment Register
0011	[7:4]	EN_OUT6 Slot Assignment Register
61h	[3:0]	EN_OUT7 Slot Assignment Register
6111	[7:4]	EN_OUT8 Slot Assignment Register
62h	[3:0]	EN_OUT9 Slot Assignment Register*
0211	[7:4]	EN_OUT10 Slot Assignment Register*
63h	[3:0]	EN_OUT11 Slot Assignment Register*
USIT	[7:4]	EN_OUT12 Slot Assignment Register *

<sup>\*</sup>MAX16047A only

Table 10. MON\_ Slot Assignment

CONFIGURATION BITS	DESCRIPTION
0000	MON_ is not assigned to a slot
0001	MON_ is assigned to Slot 1
0010	MON_ is assigned to Slot 2
0011	MON_ is assigned to Slot 3
0100	MON_ is assigned to Slot 4
0101	MON_ is assigned to Slot 5
0110	MON_ is assigned to Slot 6
0111	MON_ is assigned to Slot 7
1000	MON_ is assigned to Slot 8
1001	MON_ is assigned to Slot 9
1010	MON_ is assigned to Slot 10
1011	MON_ is assigned to Slot 11
1100	MON_ is assigned to Slot 12
1101	Not used
1110	Not used
1111	Not used

Table 11. EN\_OUT\_ Slot Assignment

CONFIGURATION BITS	DESCRIPTION
0000	EN_OUT_ is not assigned to a slot
0001	EN_OUT_ is assigned to Slot 0
0010	EN_OUT_ is assigned to Slot 1
0011	EN_OUT_ is assigned to Slot 2
0100	EN_OUT_ is assigned to Slot 3
0101	EN_OUT_ is assigned to Slot 4
0110	EN_OUT_ is assigned to Slot 5
0111	EN_OUT_ is assigned to Slot 6
1000	EN_OUT_ is assigned to Slot 7
1001	EN_OUT_ is assigned to Slot 8
1010	EN_OUT_ is assigned to Slot 9
1011	EN_OUT_ is assigned to Slot 10
1100	EN_OUT_ is assigned to Slot 11
1101	Not used
1110	Not used
1111	Not used

**Table 12. Sequence Delays and Fault Recovery** 

REGISTER/ EEPROM ADDRESS	BIT RANGE	DESCRIPTION
	[1:0]	Power-Up Fault Timeout 00 = 37.5ms 01 = 75ms 10 = 150ms 11 = 300ms
	[3:2]	Power-Down Fault Timeout  00 = 37.5ms  01 = 75ms  10 = 100ms  11 = 300ms
4Eh	[4]	INS1 Pulldown Resistor Enable 0 = Pulldown resistor for INS1 is disabled 1 = Pulldown resistor for INS1 is enabled
	[5]	INS2 Pulldown Resistor Enable 0 = Pulldown resistor for INS2 is disabled 1 = Pulldown resistor for INS2 is enabled
	[6]	INS3 Pulldown Resistor Enable 0 = Pulldown resistor for INS3 is disabled 1 = Pulldown resistor for INS3 is enabled
	[7]	INS4 Pulldown Resistor Enable 0 = Pulldown resistor for INS4 is disabled 1 = Pulldown resistor for INS4 is enabled
	[2:0]	Autoretry Timeout  000 = 20µs  001 = 18.75ms  010 = 37.5ms  011 = 75ms  100 = 150ms  101 = 300ms  110 = 600ms  111 = 2.4s
4Fh	[3]	Fault Recovery Mode 0 = Autoretry procedure is performed following a fault event 1 = Latch-off on fault
Ţ	[5:4]	Slew Rate 00 = 800V/s 01 = 400V/s 10 = 200V/s 11 = 100V/s
	[7:6]	Fault Deglitch  00 = 2 conversions  01 = 4 conversions  10 = 8 conversions  11 = 16 conversions

**Table 12. Sequence Delays and Fault Recovery (continued)** 

REGISTER/ EEPROM ADDRESS	BIT RANGE	DESCRIPTION
	[2:0]	Slot 0 Sequence Delay
50h	[5:3]	Slot 1 Sequence Delay
	[7:6]	Slot 2 Sequence Delay (LSBs)
	[0]	Slot 2 Sequence Delay (MSB)—see r50h[7:6]
51h	[3:1]	Slot 3 Sequence Delay
2111	[6:4]	Slot 4 Sequence Delay
	[7]	Slot 5 Sequence Delay (LSB)—see r52h[1:0]
52h	[1:0]	Slot 5 Sequence Delay
	[4:2]	Slot 6 Sequence Delay
	[7:5]	Slot 7 Sequence Delay
53h	[2:0]	Slot 8 Sequence Delay
	[5:3]	Slot 9 Sequence Delay
	[7:6]	Slot 10 Sequence Delay (LSBs)
	[0]	Slot 10 Sequence Delay (MSB)—see r53h[7:6]
54h	[3:1]	Slot 11 Sequence Delay
	[4]	Reverse Sequence 0 = Power down all EN_OUT_s at the same time (simultaneously) 1 = Controlled power-down will be reverse of power-up sequence
	[7:5]	Not used

**Table 13. Slot Sequence Delay Selection** 

CONFIGURATION BITS	SLOT SEQUENCE DELAY
000	20µs
001	18.75ms
010	37.5ms
011	75ms
100	150ms
101	300ms
110	600ms
111	2.4s

### Closed-Loop Tracking

The MAX16047A/MAX16049A track up to four voltages during any time slot except Slot 0 and Slot 12. Configure GPIO1–GPIO4 as sense line inputs (INS\_) to monitor tracking voltages. Configure GPIO6 as FAULTPU to indicate tracking faults, if desired. See the *General-Purpose Inputs/Outputs* section for information on configuring GPIOs.

For closed-loop tracking, use MON1, EN\_OUT1, and INS1 together to form a complete channel. Use MON2, EN\_OUT2, and INS2 to form a second complete channel. Use MON3, EN\_OUT3, and INS3 together to form a third channel. Use MON4, EN\_OUT4, and INS4 to form a fourth channel.

When configured for closed-loop tracking, assign each EN\_OUT\_ to the same slot as its associated single monitoring input (MON\_). For example, if EN\_OUT2 is assigned to Slot 3, the monitoring input is MON2 and must be assigned to Slot 3. This is because the MON\_ input, checked at the start of the slot, must be valid before tracking can begin. Tracking begins immediately and must finish before the power-up fault timeout expires, or a fault will trigger. EN\_OUT\_ configured for closed-loop tracking cannot be assigned to Slot 0.

The tracking control circuitry includes a ramp generator and a comparator control block for each tracked voltage (see the *Functional Diagram* and Figure 5). The comparator control block compares each INS\_ voltage with a control voltage ramp. If INS\_ voltages vary from the control ramp by more than 150mV (typ), the comparator control block signals an alert that dynamically stops the ramp until the slow INS\_ voltage rises to within the allowed voltage window. The total tracking time is extended under these conditions, but must still complete within the selected power-up/power-down fault timeout. The power-up/power-down tracking fault timeout period is adjustable through r4Eh[3:0].

A voltage difference between any two tracking INS\_voltages exceeding 330mV generates a tracking fault, forcing all EN\_OUT\_ voltages low and generating a fault log. If configured as FAULTPU, GPIO6 asserts when a tracking fault occurs.

The comparator control blocks also monitor INS\_ voltages with respect to input (MON\_) voltages. Under normal conditions each INS\_ tracks the control ramp until the INS\_ voltages reach the configured power-good

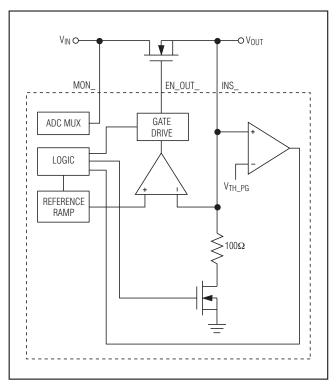


Figure 5. Closed-Loop Tracking

(PG) thresholds, set as a programmable percentage of the MON\_ voltage. Use register r64h to set the PG thresholds (Table 14). Once PG is detected, the external n-channel FET saturates with 5V (typ) applied between gate and source. The slew rate for the control ramp is programmable from 100V/s to 800V/s in r4Fh[5:4] (see Table 12).

Power-down initiates when EN is forced low or when the Software Enable bit in r4Dh[0] is set to '1.' If the Reverse Sequence bit is set (r54h[4]) INS\_ voltages follow a falling reference ramp to ground as long as MON\_ voltages remain high enough to supply the required voltage/current. If a monitored voltage drops faster than the control ramp voltage or the corresponding MON\_ voltage falls too quickly, power-down tracking operation is terminated and all EN\_OUT\_ voltages are immediately forced to ground. If the Reverse Sequence bit is set to '0,' all EN\_OUT\_ voltages are forced low simultaneously.

The MAX16047A/MAX16049A include selectable internal  $100\Omega$  pulldown resistors to ensure that tracked voltages are not held high by large external capacitors during a fault event. The pulldowns help to ensure that monitored INS\_ voltages are fully discharged before the next power-up cycle is initiated. These pulldowns are high impedance during normal operation. Set r4Eh[7:4] to '1' to enable the pulldown resistors (Table 12). These pull-

down resistors may also be used with EN\_OUT1-EN\_OUT4 channels not configured for closed-loop tracking, which is useful to discharge the output capacitors of a DC-DC converter during shutdown. For this case, configure the GPIO as an INS\_ input and set the  $100\Omega$  pulldown bit, but do not enable closed-loop tracking. Connect the INS\_ input to the output of the power supply.

Table 14. Power-Good (PG) Thresholds

REGISTER/ EEPROM ADDRESS	BIT RANGE	DESCRIPTION
64h	[1:0]	00 = PG is asserted when monitored V <sub>MON1</sub> is 95% of V <sub>INS1</sub> 01 = PG is asserted when monitored V <sub>MON1</sub> is 92.5% of V <sub>INS1</sub> 10 = PG is asserted when monitored V <sub>MON1</sub> is 90% of V <sub>INS1</sub> 11 = PG is asserted when monitored V <sub>MON1</sub> is 87.5% of V <sub>INS1</sub>
	[3:2]	00 = PG is asserted when monitored V <sub>MON2</sub> is 95% of V <sub>INS2</sub> 01 = PG is asserted when monitored V <sub>MON2</sub> is 92.5% of V <sub>INS2</sub> 10 = PG is asserted when monitored V <sub>MON2</sub> is 90% of V <sub>INS2</sub> 11 = PG is asserted when monitored V <sub>MON2</sub> is 87.5% of V <sub>INS2</sub>
	[5:4]	00 = PG is asserted when monitored V <sub>MON3</sub> is 95% of V <sub>INS3</sub> 01 = PG is asserted when monitored V <sub>MON3</sub> is 92.5% of V <sub>INS3</sub> 10 = PG is asserted when monitored V <sub>MON3</sub> is 90% of V <sub>INS3</sub> 11 = PG is asserted when monitored V <sub>MON3</sub> is 87.5% of V <sub>INS3</sub>
	[7:6]	00 = PG is asserted when monitored V <sub>MON4</sub> is 95% of V <sub>INS4</sub> 01 = PG is asserted when monitored V <sub>MON4</sub> is 92.5% of V <sub>INS4</sub> 10 = PG is asserted when monitored V <sub>MON4</sub> is 90% of V <sub>INS4</sub> 11 = PG is asserted when monitored V <sub>MON4</sub> is 87.5% of V <sub>INS4</sub>

#### **Faults**

The MAX16047A/MAX16049A monitor the input (MON\_) channels and compare the results with an overvoltage threshold, an undervoltage threshold, and a selectable overvoltage or undervoltage early warning threshold. Based on these conditions, the MAX16047A/MAX16049A can assert various fault outputs and save specific information about the channel conditions and voltages into the nonvolatile EEPROM. Once a critical fault event occurs, the failing channel condition, ADC conversions at the time of the fault, or both may be saved by configuring the event logger. The event logger records a single failure in the internal EEPROM and sets a lock bit which protects the stored fault data from accidental erasure on a subsequent power-up.

The MAX16047A/MAX16049A are capable of measuring overvoltage and undervoltage fault events. Fault conditions are detected at the end of each ADC conversion. An overvoltage event occurs when the voltage

at a monitored input exceeds the overvoltage threshold for that input. An undervoltage fault occurs when the voltage at a monitored input falls below the undervoltage threshold. Fault thresholds are set in registers r23h to r46h as shown in Table 15. Disabled inputs are not monitored for fault conditions and are skipped over by the input multiplexer. Only the upper 8 bits of a conversion result are compared with the programmed fault thresholds. Inputs not assigned to a sequencing slot are not monitored for fault conditions but are still recorded in the ADC results registers.

The general-purpose inputs/outputs (GPIO1–GPIO6) can be configured as Any\_Fault outputs or dedicated FAULT1 and FAULT2 outputs to indicate fault conditions. These fault outputs are not masked by the critical fault enable bits shown in Table 17. See the *General-Purpose Inputs/Outputs* section for more information on configuring GPIOs as fault outputs.

Table 15. Fault Thresholds

REGISTER/ EEPROM ADDRESS	DESCRIPTION
23h	MON1 Early Warning Threshold
24h	MON1 Overvoltage Threshold
25h	MON1 Undervoltage Threshold
26h	MON2 Early Warning Threshold
27h	MON2 Overvoltage Threshold
28h	MON2 Undervoltage Threshold
29h	MON3 Early Warning Threshold
2Ah	MON3 Overvoltage Threshold
2Bh	MON3 Undervoltage Threshold
2Ch	MON4 Early Warning Threshold
2Dh	MON4 Overvoltage Threshold
2Eh	MON4 Undervoltage Threshold
2Fh	MON5 Early Warning Threshold
30h	MON5 Overvoltage Threshold
31h	MON5 Undervoltage Threshold
32h	MON6 Early Warning Threshold
33h	MON6 Overvoltage Threshold
34h	MON6 Undervoltage Threshold

<sup>\*</sup>MAX16047A only

REGISTER/ EEPROM ADDRESS	DESCRIPTION
35h	MON7 Early Warning Threshold
36h	MON7 Overvoltage Threshold
37h	MON7 Undervoltage Threshold
38h	MON8 Early Warning Threshold
39h	MON8 Overvoltage Threshold
3Ah	MON8 Undervoltage Threshold
3Bh	MON9 Early Warning Threshold*
3Ch	MON9 Overvoltage Threshold*
3Dh	MON9 Undervoltage Threshold*
3Eh	MON10 Early Warning Threshold*
3Fh	MON10 Overvoltage Threshold*
40h	MON10 Undervoltage Threshold*
41h	MON11 Early Warning Threshold*
42h	MON11 Overvoltage Threshold*
43h	MON11 Undervoltage Threshold*
44h	MON12 Early Warning Threshold*
45h	MON12 Overvoltage Threshold*
46h	MON12 Undervoltage Threshold*

### Deglitch

Fault conditions are detected at the end of each conversion. If the voltage on an input falls outside a monitored threshold for one acquisition, the input multiplexer remains on that channel and performs several successive conversions. To trigger a fault, the input must stay outside the threshold for a certain number of acquisitions as determined by the deglitch setting in r4Fh[7:6] (see Table 19).

#### Fault Flags

Fault flags indicate the fault status of a particular input. The fault flag of any monitored input in the device can be read at any time from registers r18h and r19h in the extended page, as shown in Table 16. Clear a fault flag by writing a '1' to the appropriate bit in the flag register. Unlike the fault signals sent to the fault outputs, these bits are masked by the critical fault enable bits (see Table 17). The fault flag will only be set if the matching enable bit in the critical fault enable register is also set.

#### Critical Faults

If a specific input threshold is critical to the operation of the system, an automatic fault log can be configured to shut down all the EN\_OUT\_s and trigger a transfer of fault information to EEPROM. For a fault condition to trigger a critical fault, set the appropriate enable bit in registers r48h to r4Ch (see Table 17).

Logged fault information is stored in EEPROM registers r00h to r0Eh (see Table 18). Once a fault log event occurs, the EEPROM is locked and must be unlocked to enable a new fault log to be stored. Write a '1' to r5Dh[1] to unlock the EEPROM. Fault information can be configured to store ADC conversion results and/or fault flags in registers r01h and r02h. Select the critical fault configuration in r47h[1:0]. Set r47h[1:0] to '11' to turn off the fault logger. All stored ADC results are 8 bits wide.

### **Table 16. Fault Flags**

EXTENDED PAGE ADDRESS	BIT RANGE	DESCRIPTION
	[0]	1 = MON1 conversion exceeds overvoltage or undervoltage thresholds
	[1]	1 = MON2 conversion exceeds overvoltage or undervoltage thresholds
	[2]	1 = MON3 conversion exceeds overvoltage or undervoltage thresholds
18h	[3]	1 = MON4 conversion exceeds overvoltage or undervoltage thresholds
1811	[4]	1 = MON5 conversion exceeds overvoltage or undervoltage thresholds
	[5]	1 = MON6 conversion exceeds overvoltage or undervoltage thresholds
	[6]	1 = MON7 conversion exceeds overvoltage or undervoltage thresholds
	[7]	1 = MON8 conversion exceeds overvoltage or undervoltage thresholds
	[0]	1 = MON9 conversion exceeds overvoltage or undervoltage thresholds*
19h	[1]	1 = MON10 conversion exceeds overvoltage or undervoltage thresholds*
	[2]	1 = MON11 conversion exceeds overvoltage or undervoltage thresholds*
	[3]	1 = MON12 conversion exceeds overvoltage or undervoltage thresholds*
	[7:4]	Not used

<sup>\*</sup>MAX16047A only

**Table 17. Critical Fault Configuration and Enable Bits** 

REGISTER/ EEPROM ADDRESS	BIT RANGE	DESCRIPTION
47h	[1:0]	Critical Fault Log Control  00 = Failed lines and ADC conversion values save to EEPROM upon critical fault  01 = Failed line flags only saved to EEPROM upon critical fault  10 = ADC conversion values only saved to EEPROM upon critical fault  11 = No information saved upon critical fault
	[7:2]	Not used
	[0]	1 = Fault log triggered when MON1 is below its undervoltage threshold
	[1]	1 = Fault log triggered when MON2 is below its undervoltage threshold
	[2]	1 = Fault log triggered when MON3 is below its undervoltage threshold
401-	[3]	1 = Fault log triggered when MON4 is below its undervoltage threshold
48h	[4]	1 = Fault log triggered when MON5 is below its undervoltage threshold
	[5]	1 = Fault log triggered when MON6 is below its undervoltage threshold
	[6]	1 = Fault log triggered when MON6 is below its undervoltage threshold
	[7]	1 = Fault log triggered when MON8 is below its undervoltage threshold
	[0]	1 = Fault log triggered when MON9 is below its undervoltage threshold*
	[1]	1 = Fault log triggered when MON10 is below its undervoltage threshold*
	[2]	1 = Fault log triggered when MON11 is below its undervoltage threshold*
401	[3]	1 = Fault log triggered when MON12 is below its undervoltage threshold*
49h	[4]	1 = Fault log triggered when MON1 is above its overvoltage threshold
	[5]	1 = Fault log triggered when MON2 is above its overvoltage threshold
	[6]	1 = Fault log triggered when MON3 is above its overvoltage threshold
	[7]	1 = Fault log triggered when MON3 is above its overvoltage threshold
	[0]	1 = Fault log triggered when MON5 is above its overvoltage threshold
	[1]	1 = Fault log triggered when MON6 is above its overvoltage threshold
	[2]	1 = Fault log triggered when MON7 is above its overvoltage threshold
4.0.1	[3]	1 = Fault log triggered when MON8 is above its overvoltage threshold
4Ah	[4]	1 = Fault log triggered when MON9 is above its overvoltage threshold*
	[5]	1 = Fault log triggered when MON10 is above its overvoltage threshold*
	[6]	1 = Fault log triggered when MON11 is above its overvoltage threshold*
	[7]	1 = Fault log triggered when MON12 is above its overvoltage threshold*
	[0]	1 = Fault log triggered when MON1 is above/below its early earning threshold
	[1]	1 = Fault log triggered when MON2 is above/below its early warning threshold
	[2]	1 = Fault log triggered when MON3 is above/below its early warning threshold
4Bh	[3]	1 = Fault log triggered when MON4 is above/below its early warning threshold
	[4]	1 = Fault log triggered when MON5 is above/below its early warning threshold
	[5]	1 = Fault log triggered when MON6 is above/below its early warning threshold
	[6]	1 = Fault log triggered when MON7 is above/below its early warning threshold
	[7]	1 = Fault log triggered when MON8 is above/below its early warning threshold

**Table 17. Critical Fault Configuration and Enable Bits (continued)** 

REGISTER/ EEPROM ADDRESS	BIT RANGE	DESCRIPTION
	[0]	1 = Fault log triggered when MON9 is above/below its early warning threshold*
	[1]	1 = Fault log triggered when MON10 is above/below its early warning threshold*
4Ch	[2]	1 = Fault log triggered when MON11 is above/below its early warning threshold*
	[3]	1 = Fault log triggered when MON12 is above/below its early warning threshold*
	[7:4]	Not used

<sup>\*</sup>MAX16047A only

### **Table 18. Fault Log EEPROM**

EEPROM ADDRESS	BIT RANGE	DESCRIPTION
	[3:0]	Power-Up/Power-Down Fault Register
	[3.0]	Slot where power-up/power-down fault is detected
	[4]	Tracking Fault Bits
00h		If '0,' tracking fault occurred on MON1/EN_OUT1/INS1
	[5]	If '0,' tracking fault occurred on MON2/EN_OUT2/INS2
	[6]	If '0,' tracking fault occurred on MON3/EN_OUT3/INS3
	[7]	If '0,' tracking fault occurred on MON4/EN_OUT4/INS4
	[0]	If '1,' fault occurred on MON1
	[1]	If '1,' fault occurred on MON2
	[2]	If '1,' fault occurred on MON3
01h	[3]	If '1,' fault occurred on MON4
0111	[4]	If '1,' fault occurred on MON5
	[5]	If '1,' fault occurred on MON6
	[6]	If '1,' fault occurred on MON7
	[7]	If '1,' fault occurred on MON8
	[0]	If '1,' fault occurred on MON9*
	[1]	If '1,' fault occurred on MON10*
02h	[2]	If '1,' fault occurred on MON11*
	[3]	If '1,' fault occurred on MON12*
	[7:4]	Not used
03h	[7:0]	MON_ ADC Fault Information (only the 8 MSBs of converted channels are saved following a fault event)  MON1 conversion result at the time the fault log was triggered
04h	[7:0]	MON2 conversion result at the time the fault log was triggered
05h	[7:0]	MON3 conversion result at the time the fault log was triggered
06h	[7:0]	MON4 conversion result at the time the fault log was triggered
07h	[7:0]	MON5 conversion result at the time the fault log was triggered
08h	[7:0]	MON6 conversion result at the time the fault log was triggered
09h	[7:0]	MON7 conversion result at the time the fault log was triggered
0Ah	[7:0]	MON8 conversion result at the time the fault log was triggered
0Bh	[7:0]	MON9 conversion result at the time the fault log was triggered*
0Ch	[7:0]	MON10 conversion result at the time the fault log was triggered*
0Dh	[7:0]	MON11 conversion result at the time the fault log was triggered*
0Eh	[7:0]	MON12 conversion result at the time the fault log was triggered*

<sup>\*</sup>MAX16047A only

### Power-Up/Power-Down Faults

All EN\_OUTs are deasserted if an overvoltage or undervoltage fault is detected during power-up/power-down (regardless of the critical fault enable bits). Under these conditions, information of the failing slot is stored in EEPROM r00h[3:0] unless the fault register is configured not to store any information by setting r47h[1:0] to '11' (see Table 17).

If there is a tracking fault on a channel configured for closed-loop tracking, a fault log operation occurs and the bits representing the failed tracking channels are set to '0' unless the fault register is configured not to store any information by setting r47h[1:0] to '11' (see Table 17).

### Autoretry/Latch Mode

For critical faults, the MAX16047A/MAX16049A can be configured for one of two fault management methods: autoretry or latch-on-fault. Set r4Fh[3] to '0' to select autoretry mode. In this configuration, the device will shut down after a critical fault event and then restart following a configurable delay. Use r4Fh[2:0] to select an

autoretry delay from 20µs to 2.4s. See Table 19 for more information on setting the autoretry delay.

Set r4Fh[3] to '1' to select the latch-on-fault mode. In this configuration EN\_OUT\_s are deasserted after a critical fault event. The device does not re-initiate the power-up sequence until EN is toggled or the Software Enable bit is reset to '0.' See the Enable section for more information on setting the Software Enable bit.

If fault information is stored in EEPROM (see the *Critical Faults* section) and autoretry mode is selected, set an autoretry delay greater than the time required for the storing operation. If fault information is stored in EEP-ROM and latch-on-fault mode is chosen, toggle EN or reset the Software Enable bit only after the completion of the storing operation. If saving information about the failed lines only, ensure a delay of at least 90ms before the restart procedure. Otherwise, ensure a minimum 306ms timeout. This ensures that ADC conversions are completed and values are stored correctly in EEPROM. See Table 20 for more information about required fault log operation periods.

**Table 19. Fault Recovery Configuration** 

REGISTER/ EEPROM ADDRESS	BIT RANGE	DESCRIPTION
	[2:0]	Autoretry Delay  000 = 20µs  001 = 18.75ms  010 = 37.5ms  011 = 75ms  100 = 150ms  101 = 300ms  110 = 600ms  111 = 2.4s
4Fh	[3]	Fault Recovery Mode  0 = Autoretry procedure is performed following a fault event  1 = Latchoff on fault
	[5:4]	Slew Rate 00 = 800V/s 01 = 400V/s 10 = 200V/s 11 = 100V/s
	[7:6]	Fault Deglitch  00 = 2 conversions  01 = 4 conversions  10 = 8 conversions  11 = 16 conversions

Table 20. EEPROM Fault Log Operation Period

FAULT CONTROL REGISTER r47h[1:0]	DESCRIPTION	MINIMUM REQUIRED SHUTDOWN PERIOD (ms)
00	Failed lines and ADC values saved	306
01	Failed lines saved	90
10	ADC values saved	252
11	No information saved	N/A

### RESET

The reset output, RESET, is asserted during power-up/power-down and deasserts following the reset time-out period once the power-up sequence is complete. The power-up sequence is complete when any MON\_inputs assigned to Slot 12 exceed their undervoltage thresholds. If no MON\_ inputs are assigned to Slot 12, the power-up sequence is complete after the slot sequence delay is expired.

RESET is a configurable output that monitors selected MON\_ voltages during normal operation. RESET also depends on any monitoring input that has one or more critical fault enable bits set. Use r19h[1:0] to configure RESET to assert on an overvoltage fault, undervoltage fault, or both. Use r19h[3:2] to configure RESET as an active-high/active-low push-pull/open-drain output. If desired, configure GPIO4 as a manual reset input, MR, and pull MR low to assert RESET. RESET includes a programmable timeout. See Table 21 for RESET dependencies and configuration registers.

**Table 21. RESET Configuration and Dependencies** 

REGISTER/ EEPROM ADDRESS	BIT RANGE	DESCRIPTION
	[1:0]	RESET OUTPUT CONFIGURATION  00 = RESET is asserted if at least one of the selected inputs exceeds its undervoltage threshold  01 = RESET is asserted if at least one of the selected inputs exceeds its early warning threshold  10 = RESET is asserted if at least one of the selected inputs exceeds its overvoltage threshold  11 = RESET is asserted if any of the selected inputs exceeds undervoltage or overvoltage thresholds
	[2]	0 = RESET is an active-low output 1 = RESET is an active-high output
19h	[3]	0 = RESET is an push-pull output 1 = RESET is a open-drain output
	[6:4]	RESET TIMEOUT  000 = 25µs  001 = 3ms  010 = 3.75ms  011 = 150ms  100 = 300ms  101 = 600ms  110 = 1200ms  111 = 2400ms
	[7]	Reserved

Table 21 . RESET Configuration and Dependencies (continued)

REGISTER/ EEPROM ADDRESS	BIT RANGE	DESCRIPTION
[0]		RESET DEPENDENCIES  1 = RESET is dependent on MON1
	[1]	1 = RESET is dependent on MON2
	[2]	1 = RESET is dependent on MON3
1Ah	[3]	1 = RESET is dependent on MON4
	[4]	1 = RESET is dependent on MON5
	[5]	1 = RESET is dependent on MON6
	[6]	1 = RESET is dependent on MON7
	[7]	1 = RESET is dependent on MON8
	[0]	1 = RESET is dependent on MON9*
	[1]	1 = RESET is dependent on MON10*
1Bh	[2]	1 = RESET is dependent on MON11*
	[3]	1 = RESET is dependent on MON12*
	[7:4]	Reserved

<sup>\*</sup>MAX16047A only

#### Watchdog Timer

The watchdog timer can operate together with or independently of the MAX16047A/MAX16049A. When operating in dependent mode, the watchdog is not activated until the sequencing is complete and RESET is de-asserted. When operating in independent mode, the watchdog timer is independent of the sequencing operation and activates immediately after V<sub>CC</sub> exceeds the UVLO threshold and the boot phase is complete. Set r4Dh[3] to '0' to configure the watchdog in dependent mode. Set r4Dh[3] to '1' to configure the watchdog in independent mode. See Table 22 for more information on configuring the watchdog timer in dependent or independent mode.

### **Dependent Watchdog Timer Operation**

The watchdog timer can be used to monitor  $\mu P$  activity in two modes. Flexible timeout architecture provides an adjustable watchdog startup delay of up to 192s, allowing complicated systems to complete lengthy boot-up routines. An adjustable watchdog timeout allows the supervisor to provide quick alerts when processor activity fails. After each reset event (VCC drops below UVLO then returns above UVLO, software reboot, manual reset ( $\overline{MR}$ ), EN input going low then high, or watchdog reset) and once sequencing is complete, the watchdog startup delay provides an extended time for the system to power up and fully initialize all  $\mu P$  and system components before assuming responsibility for

routine watchdog updates. Set r55h[6] to '1' to enable the watchdog startup delay. Set r55h[6] to '0' to disable the watchdog startup delay.

The normal watchdog timeout period, twpl, begins after the first transition on WDI before the conclusion of the long startup watchdog period, twpl\_STARTUP (Figures 6 and 7). During the normal operating mode, WDO asserts if the µP does not toggle WDI with a valid transition (high-to-low or low-to-high) within the standard timeout period, twpl. WDO remains asserted until WDI is toggled or RESET is asserted (Figure 7).

While EN is low, or r55h[7] is a '0,' the watchdog timer is in reset. The watchdog timer does not begin counting until the power-on mode is reached and RESET is deasserted. The watchdog timer is reset and WDO deasserts any time RESET is asserted (Figure 8). The watchdog timer will be held in reset while RESET is asserted.

The watchdog can be configured to control the  $\overline{RESET}$  output as well as the WDO output.  $\overline{RESET}$  is pulsed low for the reset timeout, t<sub>RP</sub>, when the watchdog timer expires and the Watchdog  $\overline{RESET}$  Output Enable bit (r55h[7]) is set to '1.' Therefore, WDO pulses low for a short time (approximately 1 $\mu$ s) when the watchdog timer expires.  $\overline{RESET}$  is not affected by the watchdog timer when the  $\overline{RESET}$  Output Enable bit (r55h[7]) is set to '0.'

See Table 23 for more information on configuring watchdog functionality.

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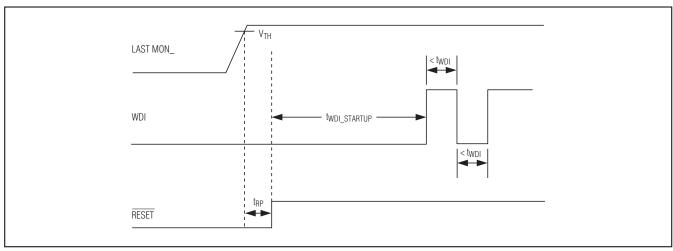


Figure 6. Normal Watchdog Startup Sequence

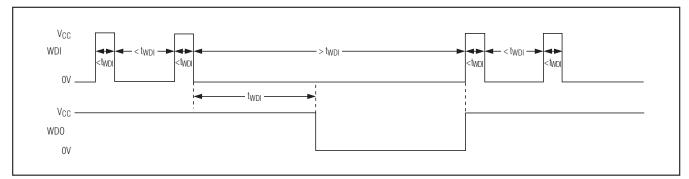


Figure 7. Watchdog Timer Operation

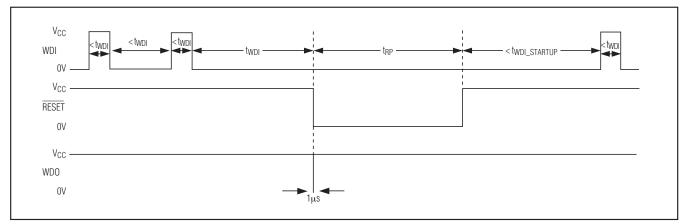


Figure 8. Watchdog Startup Sequence with Watchdog RESET Enable Bit (r55h[7]) Set to '1'

**Table 22. Watchdog Mode Selection** 

REGISTER/ EEPROM ADDRESS	BIT RANGE	DESCRIPTION
	0	Software Enable Bit 0 = Enabled. EN must also be high to begin sequencing. 1 = Disabled (factory default)
	1	Margin Bit 1 = Margin functionality is enabled 0 = Margin disabled
4Dh	2	Early Warning Selection Bit  0 = Early warning thresholds are undervoltage thresholds  1 = Early warning thresholds are overvoltage thresholds
	3	Watchdog Mode Selection Bit 0 = Watchdog timer is in dependent mode 1 = Watchdog timer is in independent mode
	[7:4]	Not used

### Table 23. Watchdog Enables and Configuration

REGISTER/EEPROM ADDRESS	BIT RANGE	DESCRIPTION
	[2:0]	Watchdog Timeout  000 = 1.5ms  001 = 6ms  010 = 18.75ms  011 = 75ms  100 = 300ms  101 = 1200ms  110 = 2400ms  111 = 4800ms
55h	[4:3]	Watchdog Startup Delay 00 = 38.4s 01 = 16.8s 10 = 153.6s 11 = 192s
	[5]	Watchdog Enable 1 = Watchdog enabled 0 = Watchdog disabled
	[6]	Watchdog Startup Delay Enable  1 = Watchdog startup delay enabled  0 = Watchdog startup delay disabled
	[7]	Watchdog RESET Output Enable  1 = Watchdog timeout asserts RESET output  0 = Watchdog timeout does not assert RESET output

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#### Independent Watchdog Timer Operation

When r4Dh[3] is '1,' the watchdog timer operates in the independent mode. In the independent mode, the watchdog timer operates as if it were a separate chip. The watchdog timer is activated immediately upon  $V_{CC}$  exceeding  $\underline{UVLO}$  and once the boot-up sequence is finished. If  $\overline{RESET}$  is asserted by the sequencer state machine, the watchdog timer and WDO will not be affected.

There will be a long startup delay if r55h[6] is a '1.' If r55h[6] is a '0,' there will not be a long startup delay.

In independent mode, if the Watchdog RESET Output Enable bit r55h[7] is set to '1,' when the watchdog timer expires, WDO will be asserted and then RESET will be asserted. WDO will then be deasserted. WDO will be

low for 3 system clock cycles or approximately 1µs. If the Watchdog RESET Output Enable bit (r55h[7]) is set to '0,' when the WDT expires, WDO will be asserted but RESET will not be affected.

### **Miscellaneous**

Table 24 lists several miscellaneous programmable items. Register r5Ch provides storage space for a user-defined configuration or firmware version number. Bit r5Dh[0] locks and unlocks the configuration registers. Bit r5Dh[1] locks and unlocks EEPROM addresses 00h to 11h. The r65h[2:0] bits contain a read-only manufacturing revision code.

Write data to EEPROM r5Dh as normally done; however, to toggle a bit in register r5Dh, write a '1' to that bit.

**Table 24. Miscellaneous Settings** 

REGISTER/ EEPROM ADDRESS	BIT RANGE	DESCRIPTION
5Ch	[7:0]	User Identification. 8 bits of memory for user-defined identification
	[0]	Configuration Lock 0 = Configuration registers and EEPROM writable 1 = Configuration registers and EEPROM [except r5Dh] locked
5Dh	[1]	EEPROM Fault Data Lock Flag (set automatically after fault log is triggered):  0 = EEPROM is not locked. A triggered fault log stores fault information to EEPROM.  1 = EEPROM addresses 00h to 11h are locked. Write a '1' to this bit to toggle the flag.
	[7:2]	Not used
65h	[2:0]	Manufacturing revision code. This register is read only. Not stored in EEPROM.
0511	[7:3]	Not used

### I<sup>2</sup>C/SMBus-Compatible Serial Interface

The MAX16047A/MAX16049A feature an I $^2$ C/SMBuscompatible 2-wire serial interface consisting of a serial data line (SDA) and a serial clock line (SCL). SDA and SCL facilitate bidirectional communication between the MAX16047A/MAX16049A and the master device at clock rates up to 400kHz. Figure 1 shows the 2-wire interface timing diagram. The MAX16047A/MAX16049A are transmit/receive slave-only devices, relying upon a master device to generate a clock signal. The master device (typically a  $\mu$ C) initiates a data transfer on the bus and generates SCL to permit that transfer.

A master device communicates to the MAX16047A/ MAX16049A by transmitting the proper address followed by command and/or data words. The slave address input, A0, is capable of detecting four different states, allowing multiple identical devices to share the same serial bus. The slave address is described further in the Slave Address section. Each transmit sequence is framed by a START (S) or REPEATED START (SR) condition and a STOP (P) condition. Each word transmitted over the bus is 8 bits long and is always followed by an acknowledge pulse. SCL is a logic input, while SDA is an open-drain input/output. SCL and SDA both require external pullup resistors to generate the logic-high voltage. Use  $4.7 \mathrm{k}\Omega$  for most applications.

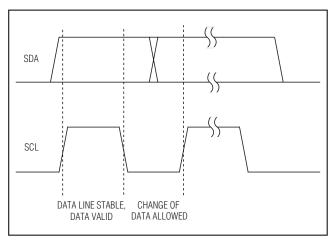


Figure 9. Bit Transfer

#### Bit Transfer

Each clock pulse transfers one data bit. The data on SDA must remain stable while SCL is high (Figure 9); otherwise the MAX16047A/MAX16049A registers a START or STOP condition (Figure 10) from the master. SDA and SCL idle high when the bus is not busy.

### START and STOP Conditions

Both SCL and SDA idle high when the bus is not busy. A master device signals the beginning of a transmission with a START condition by transitioning SDA from high to low while SCL is high. The master device issues a STOP condition by transitioning SDA from low to high while SCL is high. A STOP condition frees the bus for another transmission. The bus remains active if a REPEATED START condition is generated, such as in the block read protocol (see Figure 1).

### Early STOP Conditions

The MAX16047A/MAX16049A recognize a STOP condition at any point during transmission except if a STOP condition occurs in the same high pulse as a START condition. This condition is not a legal I<sup>2</sup>C format; at least one clock pulse must separate any START and STOP condition.

### **REPEATED START Conditions**

A REPEATED START may be sent instead of a STOP condition to maintain control of the bus during a read operation. The START and REPEATED START conditions are functionally identical.

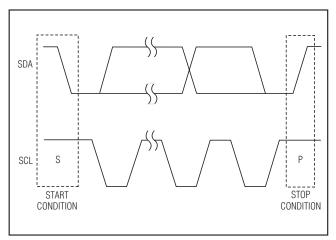


Figure 10. START and STOP Conditions

### Acknowledge

The acknowledge bit (ACK) is the 9th bit attached to any 8-bit data word. The receiving device always generates an ACK. The MAX16047A/MAX16049A generate an ACK when receiving an address or data by pulling SDA low during the 9th clock period (Figure 11). When transmitting data, such as when the master device reads data back from the MAX16047A/MAX16049A, the device waits for the master device to generate an ACK. Monitoring ACK allows for detection of unsuccessful data transfers. An unsuccessful data transfer occurs if the receiving device is busy or if a system fault has occurred. In the event of an unsuccessful data transfer, the bus master should reattempt communication at a later time. The MAX16047A/MAX16049A generate a NACK after the command byte is received during a software reboot, while writing to the EEPROM, or when receiving an illegal memory address.

#### Slave Address

Use the slave address input, A0, to allow multiple identical devices to share the same serial bus. Connect A0 to GND, DBP (or an external supply voltage greater than 2V), SCL, or SDA to set the device address on the bus. See Table 25 for a listing of all possible 7-bit addresses.

## Table 25. Setting the I<sup>2</sup>C/SMBus Slave Address

A0	SLAVE ADDRESS
0	1010 00XR
1	1010 01XR
SCL	1010 10XR
SDA	1010 11XR

X = Don't care, R = Read/write select bit.

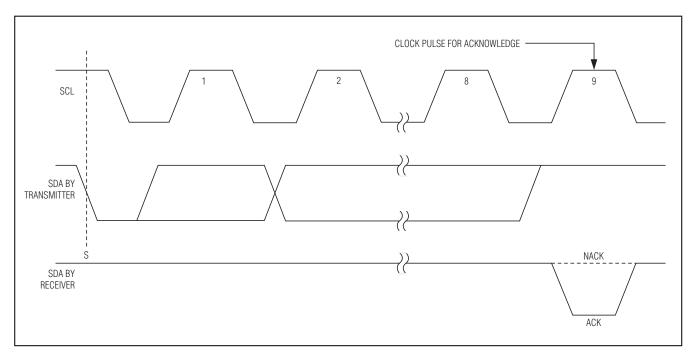


Figure 11. Acknowledge

### Send Byte

The send byte protocol allows the master device to send one byte of data to the slave device (see Figure 12). The send byte presets a register pointer address for a subsequent read or write. The slave sends a NACK instead of an ACK if the master tries to send a memory address or command code that is not allowed. If the master sends 94h or 95h, the data is ACK, because this could be the start of the write block or read block. If the master sends a STOP condition before the slave asserts on ACK, the internal address pointer does not change. If the master sends 96h, this signifies a software reboot. The send byte procedure is the following:

- 1) The master sends a START condition.
- The master sends the 7-bit slave address and a write bit (low).
- 3) The addressed slave asserts an ACK on SDA.
- The master sends an 8-bit memory address or command code.
- The addressed slave asserts an ACK (or NACK) on SDA.
- 6) The master sends a STOP condition.

### Receive Byte

The receive byte protocol allows the master device to read the register content of the MAX16047A/MAX16049A (see Figure 12). The EEPROM or register address must be preset with a send byte or write word protocol first. Once the read is complete, the internal pointer increases by one. Repeating the receive byte protocol reads the contents of the next address. The receive byte procedure follows:

- 1) The master sends a START condition.
- 2) The master sends the 7-bit slave address and a read bit (high).
- 3) The addressed slave asserts an ACK on SDA.
- 4) The slave sends 8 data bits.
- 5) The master asserts a NACK on SDA.
- 6) The master generates a STOP condition.

### Write Byte

The write byte protocol (see Figure 12) allows the master device to write a single byte in the default page, extended page, or EEPROM page, depending on which page is currently selected. The write byte procedure is the following:

- 1) The master sends a START condition.
- The master sends the 7-bit slave address and a write bit (low).
- 3) The addressed slave asserts an ACK on SDA.
- 4) The master sends an 8-bit memory address.
- 5) The addressed slave asserts an ACK on SDA.
- 6) The master sends an 8-bit data byte.
- 7) The addressed slave asserts an ACK on SDA.
- 8) The master sends a STOP condition.

To write a single byte, only the 8-bit memory address and a single 8-bit data byte are sent. The data byte is written to the addressed location if the memory address is valid. The slave will assert a NACK at step 5 if the memory address is not valid.

#### Read Byte

The read byte protocol (see Figure 12) allows the master device to read a single byte located in the default page, extended page, or EEPROM page depending on which page is currently selected. The read byte procedure is the following:

- 1) The master sends a START condition.
- 2) The master sends the 7-bit slave address and a write bit (low).
- 3) The addressed slave asserts an ACK on SDA.
- 4) The master sends an 8-bit memory address.
- 5) The addressed slave asserts an ACK on SDA.
- 6) The master sends a REPEATED START condition.
- 7) The master sends the 7-bit slave address and a read bit (high).
- 8) The addressed slave asserts an ACK on SDA.
- 9) The slave sends an 8-bit data byte.
- 10) The master asserts a NACK on SDA.
- 11) The master sends a STOP condition.

If the memory address is not valid, it is NACKed by the slave at step 5 and the address pointer is not modified.

#### **Command Codes**

The MAX16047A/MAX16049A use eight command codes for block read, block write, and other commands. See Table 26 for a list of command codes.

To initiate a software reboot, send 96h using the send byte format. A software-initiated reboot is functionally the same as a hardware-initiated power-on reset. During boot-up, EEPROM configuration data in the range of 0Fh to 7Dh is copied to the same register addresses in the default page.

Send command code 97h to trigger a fault store to EEPROM. Configure the Critical Fault Log Control register (r47h) to store ADC conversion results and/or fault flags in registers once the command code has been sent.

Using command code 98h allows access to the extended page, which contains registers for ADC conversion results, and GPIO input/output data. Use command code 99h to return to the default page.

Send command code 9Ah to access the EEPROM page. Once command code 9Ah has been sent, all addresses are recognized as EEPROM addresses only. Send command code 9Bh to return to the default page.

Table 26. Command Codes

COMMAND CODE	ACTION
94h	Write Block
95h	Read Block
96h	Reboot EEPROM in Register File
97h	Trigger Fault Store to EEPROM
98h	Extended Page Access On
99h	Extended Page Access Off
9Ah	EEPROM Page Access On
9Bh	EEPROM Page Access Off

#### **Block Write**

The block write protocol (see Figure 12) allows the master device to write a block of data (1 byte to 16 bytes) to memory. The destination address should be preloaded by a previous send byte command; otherwise the block write command begins to write at the current address pointer. After the last byte is written, the address pointer remains preset to the next valid address. If the number of bytes to be written causes the address pointer to exceed FFh for EEPROM or 7Dh for configuration registers, the address pointer stays at FFh or 7Dh, overwriting this memory address with the

remaining bytes of data. The last data byte sent is stored at register address FFh. The slave generates a NACK at step 5 if the command code is invalid or if the device is busy, and the address pointer is not altered. The block write procedure is the following:

- 1) The master sends a START condition.
- 2) The master sends the 7-bit slave address and a write bit (low).
- 3) The addressed slave asserts an ACK on SDA.
- 4) The master sends the 8-bit command code for block write (94h).
- 5) The addressed slave asserts an ACK on SDA.
- 6) The master sends the 8-bit byte count (1 byte to 16 bytes), *n*.
- 7) The addressed slave asserts an ACK on SDA.
- 8) The master sends 8 bits of data.
- 9) The addressed slave asserts an ACK on SDA.
- 10) Repeat steps 8 and 9 n 1 times.
- 11) The master sends a STOP condition.

### **Block Read**

The block read protocol (see Figure 12) allows the master device to read a block of up to 16 bytes from memory. Read fewer than 16 bytes of data by issuing an early STOP condition from the master or by generating a NACK with the master. The destination address should be preloaded by a previous send byte command; otherwise the block read command begins to read at the current address pointer. If the number of bytes to be read causes the address pointer to exceed FFh for the configuration register or EEPROM, the address pointer stays at FFh and the last data byte read is from register rFFh. The block read procedure is the following:

- 1) The master sends a START condition.
- 2) The master sends the 7-bit slave address and a write bit (low).
- 3) The addressed slave asserts an ACK on SDA.
- 4) The master sends 8 bits of the block read command (95h).
- 5) The slave asserts an ACK on SDA, unless busy.
- 6) The master generates a REPEATED START condition.
- 7) The master sends the 7-bit slave address and a read bit (high).

- 8) The slave asserts an ACK on SDA.
- 9) The slave sends the 8-bit byte count (16).
- 10) The master asserts an ACK on SDA.
- 11) The slave sends 8 bits of data.

- 12) The master asserts an ACK on SDA.
- 13) Repeat steps 11 and 12 up to fifteen times.
- 14) The master asserts a NACK on SDA.
- 15) The master sends a STOP condition.

S	ADDRESS	WR	ACK	DATA	ACK	Р				S	ADD	RESS	WR	ACK	DATA	NACK	Р				
Ī	7 BITS	0		8 BITS		<b>A</b>				$\Box$	7.6	BITS	1		8 BITS		<b></b>	1			
	SLAVE ADDRE EQUIVALENT SELECT LINE 3-WIRE INTER	TO CHI OF A FACE.	<u> </u>	DATA BYTE: P INTERNAL AD OR REPRESEN	DRESS	POINT					SLAVE EQUIV SELEC	E ADDRI ALENT CT LINE E INTER	TO CH OF A		DATA BYTE INTERNAL A OR REPRES	ADDRES	S POII	NTER			
S	ADDRESS		WR	ACK CON	MMANIF		ICK	DATA		AC	K F										
<u></u>																		SLAVE	E TO MASTER		
<u> </u>	7 BITS		0	COMM	BITS	/TF		8 BIT ATA BYTE		A COE	T OTIAL 2										
	3-WIRE INTER  BYTE FORM.	FACE.		EEPRO YOU AI			0.	ET BY TH	E CON	MMAN	D BYTE.							MAST	ER TO SLAVE		
S	SLAVE ADDRESS	WR	ACK	COMMAND	ACK	SR	SLA ADDR		WR .	ACK	DATA B	YTE N	IACK	Р							
<b>\</b>	7 BITS	0		8 BITS		<b>+</b>	7 BI	ITS	1		8 BI	ΓS		1							
	SLAVE ADDRE EQUIVALENT SELECT LINE 3-WIRE INTER	ΓΟ CHI OF A FACE.		COMMAND B PREPARES DE FOR FOLLOW READ.	VICE	;	EQUIVAL SELECT 3-WIRE	ADDRESS LENT TO LINE OF INTERFA	CHIP- A CE.	-	DATA BY FROM T THE COI	HE REG MMANI	SISTER D BYTE	SET BY				_			
S	ADDRESS	WR	ACK	COMMAND	ACK		YTE NT= N	ACK	Data i 1	BYTE	ACK	DATA E	BYTE	ACK	DATA BYTE N	ACK	Р				
<b>\</b>	7 BITS	0		8 BITS		8 E	BITS		8 BI	ITS		8 BI	ITS		8 BITS		1				
	SLAVE ADDRE EQUIVALENT SELECT LINE	TO CHI OF A	P-	COMMAND E DESTINATION ADDRESS			·		OMM		ATA GO	ES INTO	O THE I	REGIST	ER SET BY T	HE		-			
	3-WIRE INTER																				
LOC	3-WIRE INTER	MAT					l	.		ACK	BYT		ACK	DATA B	YTE ACK	DATA B	YTE	ACK	DATA BYTE	NACK	Р
S <b>LOC</b>		WAT WR	ACK	COMMAND	ACK	SR	ADDR	ESS \	WR A	AUN	COUNT	= N /	AUI	1	71011				N	1.0.0	
	K READ FOR		ACK	COMMAND 8 BITS	ACK	SR	ADDR 7 BI		1	AUN	8 BIT	= IV	AOIX	8 BI		8 BI	ΓS		8 BITS		1
	K READ FORI	WR 0 ESS: TO CHI OF A			YTE:	<b>↓</b>	7 BI SLAVE A EQUIVAL SELECT		1 S: CHIP-		8 BIT	TE: DAT	TA IS RI	EAD FR		L GISTER (0	DR				<b>†</b>

Figure 12. I<sup>2</sup>C/SMBus Protocols

#### **JTAG Serial Interface**

The MAX16047A/MAX16049A contain a JTAG port that complies with a subset of the IEEE 1149.1 specification. Either the I<sup>2</sup>C or the JTAG interface may be used to access internal memory; however, only one interface is allowed to run at a time. The MAX16047A/

MAX16049A do not support IEEE 1149.1 boundary-scan functionality. The MAX16047A/MAX16049A contain extra JTAG instructions and registers not included in the JTAG specification that provide access to internal memory. The extra instructions include LOAD ADDRESS, WRITE DATA, READ DATA, REBOOT, SAVE, and USERCODE.

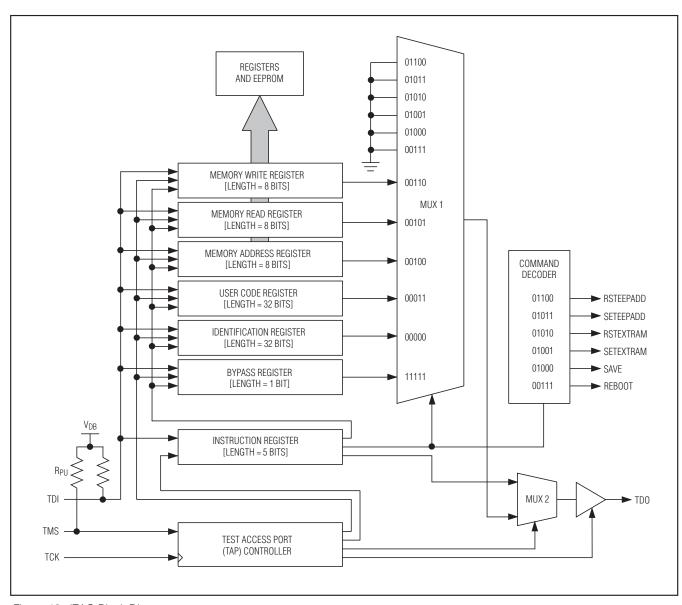


Figure 13. JTAG Block Diagram

### Test Access Port (TAP) Controller State Machine

The TAP controller is a finite state machine that responds to the logic level at TMS on the rising edge of TCK. See Figure 14 for a diagram of the finite state machine. The possible states are described below:

**Test-Logic-Reset:** At power-up, the TAP controller is in the test-logic-reset state. The instruction register contains the IDCODE instruction. All system logic of the device operates normally. This state can be reached from any state by driving TMS high for five clock cycles.

**Run-Test/Idle:** The run-test/idle state is used between scan operations or during specific tests. The instruction register and test data registers remain idle.

**Select-DR-Scan:** All test data registers retain their previous state. With TMS low, a rising edge of TCK moves the controller into the capture-DR state and initiates a scan sequence. TMS high during a rising edge on TCK moves the controller to the select-IR-scan state.

**Capture-DR:** Data can be parallel-loaded into the test data registers selected by the current instruction. If the instruction does not call for a parallel load or the selected test data register does not allow parallel loads, the test data register remains at its current value. On the rising edge of TCK, the controller goes to the shift-DR state if TMS is low or it goes to the exit1-DR state if TMS is high.

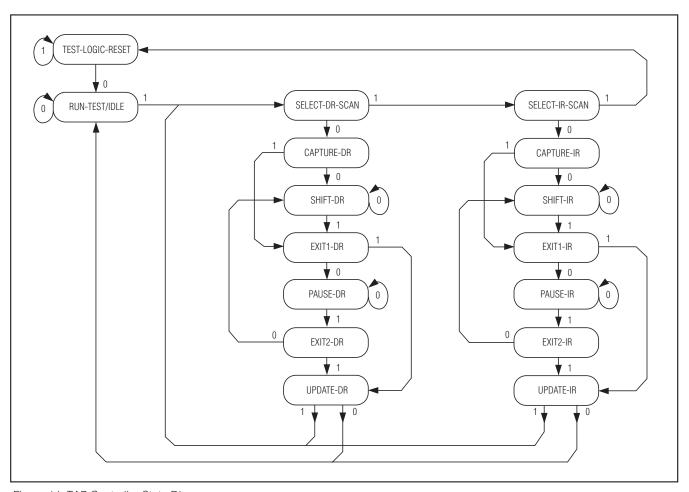


Figure 14. TAP Controller State Diagram

**Shift-DR:** The test data register selected by the current instruction connects between TDI and TDO and shifts data one stage toward its serial output on each rising edge of TCK while TMS is low. On the rising edge of TCK, the controller goes to the exit1-DR state if TMS is high.

**Exit1-DR:** While in this state, a rising edge on TCK puts the controller in the update-DR state. A rising edge on TCK with TMS low puts the controller in the pause-DR state

**Pause-DR:** Shifting of the test data registers halts while in this state. All test data registers retain their previous state. The controller remains in this state while TMS is low. A rising edge on TCK with TMS high puts the controller in the exit2-DR state.

**Exit2-DR:** A rising edge on TCK with TMS high while in this state puts the controller in the update-DR state. A rising edge on TCK with TMS low enters the shift-DR state.

**Update-DR:** A falling edge on TCK while in the update-DR state latches the data from the shift register path of the test data registers into a set of output latches. This prevents changes at the parallel output because of changes in the shift register. On the rising edge of TCK, the controller goes to the run-test/idle state if TMS is low or goes to the select-DR-scan state if TMS is high.

**Select-IR-Scan:** All test data registers retain their previous states. The instruction register remains unchanged during this state. With TMS low, a rising edge on TCK moves the controller into the capture-IR state. TMS high during a rising edge on TCK puts the controller back into the test-logic-reset state.

**Capture-IR:** Use the capture-IR state to load the shift register in the instruction register with a fixed value. This value is loaded on the rising edge of TCK. If TMS is high on the rising edge of TCK, the controller enters the exit1-IR state. If TMS is low on the rising edge of TCK, the controller enters the shift-IR state.

**Shift-IR:** In this state, the shift register in the instruction register connects between TDI and TDO and shifts data one stage for every rising edge of TCK toward the TDO serial output while TMS is low. The parallel outputs

of the instruction register as well as all test data registers remain at their previous states. A rising edge on TCK with TMS high moves the controller to the exit1-IR state. A rising edge on TCK with TMS low keeps the controller in the shift-IR state while moving data one stage through the instruction shift register.

**Exit1-IR:** A rising edge on TCK with TMS low puts the controller in the pause-IR state. If TMS is high on the rising edge of TCK, the controller enters the update-IR state.

**Pause-IR:** Shifting of the instruction shift register halts temporarily. With TMS high, a rising edge on TCK puts the controller in the exit2-IR state. The controller remains in the pause-IR state if TMS is low during a rising edge on TCK.

**Exit2-IR:** A rising edge on TCK with TMS high puts the controller in the update-IR state. The controller loops back to shift-IR if TMS is low during a rising edge of TCK in this state.

**Update-IR:** The instruction code that has been shifted into the instruction shift register latches to the parallel outputs of the instruction register on the falling edge of TCK as the controller enters this state. Once latched, this instruction becomes the current instruction. A rising edge on TCK with TMS low puts the controller in the run-test/idle state. With TMS high, the controller enters the select-DR-scan state.

### Instruction Register

The instruction register contains a shift register as well as a latched parallel output and is 5 bits in length. When the TAP controller enters the shift-IR state, the instruction shift register connects between TDI and TDO. While in the shift-IR state, a rising edge on TCK with TMS low shifts the data one stage toward the serial output at TDO. A rising edge on TCK in the exit1-IR state or the exit2-IR state with TMS high moves the controller to the update-IR state. The falling edge of that same TCK latches the data in the instruction shift register to the instruction register parallel output. Instructions supported by the MAX16047A/MAX16049A and the respective operational binary codes are shown in Table 27.

**Table 27. JTAG Instruction Set** 

INSTRUCTION	HEX CODE	SELECTED REGISTER/ACTION
BYPASS	1Fh	Bypass. Mandatory instruction code.
IDCODE	00h	Manufacturer ID code and part number
USERCODE	03h	User code (user-defined ID)
LOAD ADDRESS	04h	Load address register content
READ DATA	05h	Memory read
WRITE DATA	06h	Memory write
REBOOT	07h	Resets the device
SAVE	08h	Stores current fault information in EEPROM
SETEXTRAM	09h	Extended page access on
RSTEXTRAM	0Ah	Extended page access off
SETEEPADD	0Bh	EEPROM page access on
RSTEEPADD	0Ch	EEPROM page access off

**BYPASS:** When the BYPASS instruction is latched into the instruction register, TDI connects to TDO through the 1-bit bypass test data register. This allows data to pass from TDI to TDO without affecting the device's normal operation.

**IDCODE:** When the IDCODE instruction is latched into the parallel instruction register, the identification data register is selected. The device identification code is loaded into the identification data register on the rising

edge of TCK following entry into the capture-DR state. Shift-DR can be used to shift the identification code out serially through TDO. During test-logic-reset, the IDCODE instruction is forced into the instruction register. The identification code always has a '1' in the LSB position. The next 11 bits identify the manufacturer's JEDEC number and number of continuation bytes followed by 16 bits for the device and 4 bits for the version. See Table 28.

### Table 28, 32-Bit Identification Code

MSB L						
Version (4 bits)	Device ID (16 bits)	Manufacturer ID (11 bits)	Fixed value (1 bit)			
0000	000000000000001	00011001011	1			

**USERCODE:** When the USERCODE instruction latches into the parallel instruction register, the user-code data register is selected. The device user-code loads into the user-code data register on the rising edge of TCK following entry into the capture-DR state. Shift-DR can

be used to shift the user-code out serially through TDO. See Table 29. This instruction may be used to help identify multiple MAX16047A/MAX16049A devices connected in a JTAG chain.

### Table 29, 32-Bit User-Code Data

MSB					
D.C. (don't cares)	I <sup>2</sup> C/SMBus slave address	User identification (firmware version)			
000000000000000	See Table 31	r5Ch[7:0] contents			

**LOAD ADDRESS:** This is an extension to the standard IEEE 1149.1 instruction set to support access to the memory in the MAX16047A/MAX16049A. When the LOAD ADDRESS instruction latches into the instruction register, TDI connects to TDO through the 8-bit memory address test data register during the shift-DR state.

**READ DATA:** This is an extension to the standard IEEE 1149.1 instruction set to support access to the memory in the MAX16047A/MAX16049A. When the READ DATA instruction latches into the instruction register, TDI connects to TDO through the 8-bit memory read test data register during the shift-DR state.

**WRITE DATA:** This is an extension to the standard IEEE 1149.1 instruction set to support access to the memory in the MAX16047A/MAX16049A. When the WRITE DATA instruction latches into the instruction register, TDI connects to TDO through the 8-bit memory write test data register during the shift-DR state.

**REBOOT:** This is an extension to the standard IEEE 1149.1 instruction set to initiate a software controlled reset to the MAX16047A/MAX16049A. When the REBOOT instruction latches into the instruction register, the MAX16047A/MAX16049A resets and immediately begins the boot-up sequence.

**SAVE:** This is an extension to the standard IEEE 1149.1 instruction set that triggers a fault log. The current ADC conversion results along with fault information are saved to EEPROM depending on the configuration of the Critical Fault Log Control register (r47h).

**SETEXTRAM:** This is an extension to the standard IEEE 1149.1 instruction set that allows access to the extended page. Extended registers include ADC conversion results and GPIO input/output data.

**RSTEXTRAM:** This is an extension to the standard IEEE 1149.1 instruction set. Use RSTEXTRAM to return to the default page and disable access to the extended page.

**SETEEPADD:** This is an extension to the standard IEEE 1149.1 instruction set that allows access to the EEPROM page. Once the SETEEPADD command has been sent, all addresses are recognized as EEPROM addresses only. User EEPROM (r9Ch to rFFh) cannot be accessed from the JTAG interface. Use the SMBus interface to access user EEPROM.

**RSTEEPADD:** This is an extension to the standard IEEE 1149.1 instruction set. Use RSTEEPADD to return to the default page and disable access to the EEPROM.

### Applications Information

### **Unprogrammed Device Behavior**

When the EEPROM has not been programmed using the JTAG or I<sup>2</sup>C interface, the default configuration of the EN\_OUT\_ outputs is open-drain active-low. If it is necessary to hold an EN\_OUT\_ high or low to prevent premature startup of a power supply before the EEPROM is programmed, connect a resistor to ground or the supply voltage. Avoid connecting a resistor to ground if the output is to be configured as open-drain with a separate pullup resistor.

### **Device Behavior at Power-Up**

When VCC is ramped from 0V, the RESET output is high impedance until VCC reaches 1.4V, at which point it is driven low. All other outputs are high impedance until VCC reaches 2.85V, when the EEPROM contents are copied into register memory, and after which the outputs assume their programmed states. If EN is driven by external logic instead of from the center tap of a VCC-connected resistive divider, ensure that an active-high pulse occurs on EN within 1.5ms of VCC exceeding 2.85V. If the external driving logic is in the high-impedance state during power-up, this pulse can be created by connecting an external pullup resistor to EN

### Maintaining Power During a Fault Condition

Power to the MAX16047A/MAX16049A must be maintained for a specific period of time to ensure a successful EEPROM fault log operation during a fault that removes power to the circuit. The amount of time required depends on the settings in the fault control register (r47h[1:0]) according to Table 30.

## Table 30. EEPROM Fault Log Operation Period

FAULT CONTROL REGISTER VALUE r47h[1:0]	DESCRIPTION	REQUIRED PERIOD tFAULT_SAVE (ms)
00	Failed lines and ADC values saved	306
01	Failed lines saved	90
10	ADC values saved	252
11	No information saved	_

Maintain power for shutdown during fault conditions in applications where the always-on power supply cannot be relied upon by placing a diode and a large capaci-

tor between the voltage source,  $V_{IN}$ , and  $V_{CC}$  (Figure 15). The capacitor value depends on  $V_{IN}$  and the time delay required, tfault\_save. Use the following formula to calculate the capacitor size:

$$C = \frac{t_{FAULT\_SAVE} \times l_{CC(MAX)}}{v_{IN} - v_{DIODE} - v_{CC(MIN)}}$$

where the capacitance is in Farads and tFAULT\_SAVE is in seconds. ICC(MAX) is 5mA, VDIODE is the voltage drop across the diode, and VUVLO is 2.85V. For example, with a VIN of 14V, a diode drop of 0.7V, and a tFAULT\_SAVE of 0.306s, the minimum required capacitance is 190 $\mu$ F.

### **Driving High-Side MOSFET Switches**

The MAX16047A/MAX16049A use external n-channel MOSFET switches for voltage tracking applications. To configure the part for closed-loop voltage tracking using series-pass MOSFETs, configure up to four of the programmable outputs (EN OUT1-EN OUT4) of the MAX16047A/MAX16049A as closed-loop tracking outputs and configure up to four of the GPIOs as sense-return inputs (INS1-INS4). Connect the EN\_OUT\_ output to the gate of an n-channel MOSFET, connect the source of the MOSFET to the INS\_ feedback input, and monitor the drain side of the MOSFET with the corresponding MON\_ input (see Figure 16). Both the input and the output must be assigned to the same slot (see the Closed-Loop Tracking section). Configure the power-up and powerdown slew rates in the configuration registers. To provide additional control over power-down, enable the internal  $100\Omega$  pulldown resistors on the INS connections.

Up to six of the programmable outputs (EN\_OUT1-EN\_OUT6) of the MAX16047A/MAX16049A may be configured as charge-pump outputs. In this case, they can drive the gates of series-pass n-channel MOSFETS without closed-loop tracking functionality. When configured in this way, these outputs act as simple power switches to turn on the voltage supply rails. Approximate the slew rate, SR, using the following formula:

$$SR = \frac{I_{CP}}{\left(C_{GATE} + C_{EXT}\right)}$$

where ICP is the  $6\mu A$  (typ) charge-pump source current, CGATE is the gate capacitance of the MOSFET, and CEXT is the capacitance connected from the gate to ground. Power-down is not well controlled due to the absence of the  $100\Omega$  pulldowns.

If more than six series-pass MOSFETs are required for an application, additional series-pass p-channel MOSFETs may be connected to outputs configured as active-low open drain (Figure 17). Connect a pullup resistor from the gate to the source of the MOSFET and ensure the absolute maximum ratings of the MAX16047A/MAX16049A are not exceeded.

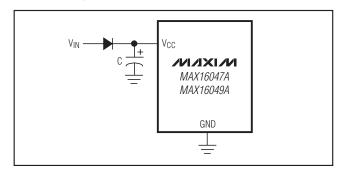


Figure 15. Power Circuit for Shutdown During Fault Conditions

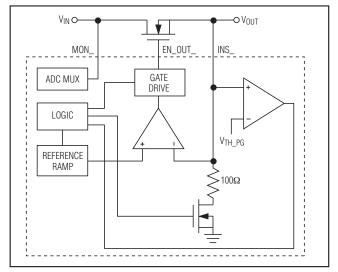


Figure 16. Closed-Loop Tracking

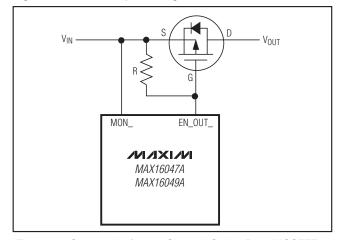


Figure 17. Connection for a p-Channel Series-Pass MOSFET

Simple slew-rate control is accomplished by adding a capacitor from the gate to ground. The slew rate is approximated by the RC charge curve of the pullup resistor acting with the capacitor from gate to ground. Note that the power-off is not well controlled due to the absence of the  $100\Omega$  pulldowns.

Ensure that MOSFETs have a low gate-to-source threshold (VGS\_TH) and RDS(ON). See Table 31 for recommended n-channel MOSFETs.

### **Layout and Bypassing**

Bypass DBP and ABP each with a 1 $\mu$ F ceramic capacitor to GND. Bypass V<sub>CC</sub> with a 10 $\mu$ F capacitor to ground. Avoid routing digital return currents through a sensitive analog area, such as an analog supply input return path or ABP's bypass capacitor ground connection. Use dedicated analog and digital ground planes. Connect the capacitors as close as possible to the device.

**Table 31. Recommended MOSFETs** 

MANUFACTURER	PART	MAX V <sub>DS</sub> (V)	V <sub>GS_</sub> TH (V)	$R_{DS(ON)}$ AT $V_{GS} = 4.5V$ $(m\Omega)$	I <sub>MAX</sub> AT 50mV VOLTAGE DROP (A)	Qg (typ) (nC)	PACKAGE
	FDC633N	30	0.67	42	1.19	11	Super SOT-6
Fairchild	FDP8030L FDB8030L	30	1.5	4.5	11.11	120	TO-220 TO-263AB
	FDD6672A	30	1.2	9.5	5.26	33	TO-252
	FDS8876	30	2.5	10.2	2.94	15	SO-8
	Si7136DP	20	3	4.5	11.11	24.5	SO-8
	Si4872DY	30	1	10	5	27	SO-8
Vishay	SUD50N02-09P	20	3	17	2.94	10.5	TO-252
	Si1488DH	20	0.95	49	1.02	6	SOT-363 SC70-6
	IRL3716	20	3	4.8	10.4	53	TO220AB D <sup>2</sup> PAK TO-262
International	IRL3402	20	0.7	10	5	78 (max)	TO220AB
Rectifier	IRL3715Z	20	2.1	15.5	3.22	7	TO220AB D <sup>2</sup> PAK TO-262
	IRLM2502	20	1.2	45	1.11	8	SOT23-3 Micro3

### Register Map

PAGE	ADDRESS	READ/WRITE	DESCRIPTION
Ext	00h	R	MON1 ADC Result Register (MSB)
Ext	01h	R	MON1 ADC Result Register (LSB)
Ext	02h	R	MON2 ADC Result Register (MSB)
Ext	03h	R	MON2 ADC Result Register (LSB)
Ext	04h	R	MON3 ADC Result Register (MSB)
Ext	05h	R	MON3 ADC Result Register (LSB)
Ext	06h	R	MON4 ADC Result Register (MSB)
Ext	07h	R	MON4 ADC Result Register (LSB)
Ext	08h	R	MON5 ADC Result Register (MSB)
Ext	09h	R	MON5 ADC Result Register (LSB)
Ext	0Ah	R	MON6 ADC Result Register (MSB)
Ext	0Bh	R	MON6 ADC Result Register (LSB)
Ext	0Ch	R	MON7 ADC Result Register (MSB)
Ext	0Dh	R	MON7 ADC Result Register (LSB)
Ext	0Eh	R	MON8 ADC Result Register (MSB)
Ext	0Fh	R	MON8 ADC Result Register (LSB)
Ext	10h	R	MON9 ADC Result Register (MSB)*
Ext	11h	R	MON9 ADC Result Register (LSB)*
Ext	12h	R	MON10 ADC Result Register (MSB)*
Ext	13h	R	MON10 ADC Result Register (LSB)*
Ext	14h	R	MON11 ADC Result Register (MSB)*
Ext	15h	R	MON11 ADC Result Register (LSB)*
Ext	16h	R	MON12 ADC Result Register (MSB)*
Ext	17h	R	MON12 ADC Result Register (LSB)*
Ext	18h	R/W	Fault Register—Failed Line Flags
Ext	19h	R/W	Fault Register—Failed Line Flags
Ext	1Ah	R/W	GPIO Data Out
Ext	1Bh	R	GPIO Data In
Ext	1Ch-1Dh	R/W	Reserved
Default	00h-0Bh	R/W	Reserved
EEPROM	00h	R/W	Power-Up Fault Registers
EEPROM	01h	R/W	Failed Line Flags (Fault Registers)
EEPROM	02h	R/W	Failed Line Flags (Fault Registers)
EEPROM	03h	R/W	MON1 Conversion Result at Time of Fault
EEPROM	04h	R/W	MON2 Conversion Result at Time of Fault
EEPROM	05h	R/W	MON3 Conversion Result at Time of Fault
EEPROM	06h	R/W	MON4 Conversion Result at Time of Fault
EEPROM	07h	R/W	MON5 Conversion Result at Time of Fault
EEPROM	08h	R/W	MON6 Conversion Result at Time of Fault
EEPROM	09h	R/W	MON7 Conversion Result at Time of Fault

### Register Map (continued)

PAGE	ADDRESS	READ/WRITE	DESCRIPTION
EEPROM	0Ah	R/W	MON8 Conversion Result at Time of Fault
EEPROM	0Bh	R/W	MON9 Conversion Result at Time of Fault*
EEPROM	0Ch	R/W	MON10 Conversion Result at Time of Fault*
EEPROM	0Dh	R/W	MON11 Conversion Result at Time of Fault*
EEPROM	0Eh	R/W	MON12 Conversion Result at Time of Fault*
Def/EE	0Fh	R/W	ADC MON4–MON1 Voltage Ranges
Def/EE	10h	R/W	ADC MON8-MON5 Voltage Ranges
Def/EE	11h	R/W	ADC MON12-MON9 Voltage Ranges*
Def/EE	12h-14h	R/W	Reserved
Def/EE	15h	R/W	FAULT1 Dependencies
Def/EE	16h	R/W	FAULT1 Dependencies
Def/EE	17h	R/W	FAULT2 Dependencies
Def/EE	18h	R/W	FAULT2 Dependencies
Def/EE	19h	R/W	RESET Output Configuration
Def/EE	1Ah	R/W	RESET Output Dependencies
Def/EE	1Bh	R/W	RESET Output Dependencies
Def/EE	1Ch	R/W	GPIO Configuration
Def/EE	1Dh	R/W	GPIO Configuration
Def/EE	1Eh	R/W	GPIO Configuration
Def/EE	1Fh	R/W	EN_OUT1-EN_OUT3 Output Configuration
Def/EE	20h	R/W	EN_OUT3-EN_OUT6 Output Configuration
Def/EE	21h	R/W	EN_OUT6-EN_OUT9 Output Configuration*
Def/EE	22h	R/W	EN_OUT10-EN_OUT12 Output Configuration*
Def/EE	23h	R/W	MON1 Early Warning Threshold
Def/EE	24h	R/W	MON1 Overvoltage Threshold
Def/EE	25h	R/W	MON1 Undervoltage Threshold
Def/EE	26h	R/W	MON2 Early Warning Threshold
Def/EE	27h	R/W	MON2 Overvoltage Threshold
Def/EE	28h	R/W	MON2 Undervoltage Threshold
Def/EE	29h	R/W	MON3 Early Warning Threshold
Def/EE	2Ah	R/W	MON3 Overvoltage Threshold
Def/EE	2Bh	R/W	MON3 Undervoltage Threshold
Def/EE	2Ch	R/W	MON4 Early Warning Threshold
Def/EE	2Dh	R/W	MON4 Overvoltage Threshold
Def/EE	2Eh	R/W	MON4 Undervoltage Threshold
Def/EE	2Fh	R/W	MON5 Early Warning Threshold
Def/EE	30h	R/W	MON5 Overvoltage Threshold
Def/EE	31h	R/W	MON5 Undervoltage Threshold
Def/EE	32h	R/W	MON6 Early Warning Threshold
Def/EE	33h	R/W	MON6 Overvoltage Threshold

### Register Map (continued)

PAGE	ADDRESS	READ/WRITE	DESCRIPTION
Def/EE	34h	R/W	MON6 Undervoltage Threshold
Def/EE	35h	R/W	MON7 Early Warning Threshold
Def/EE	36h	R/W	MON7 Overvoltage Threshold
Def/EE	37h	R/W	MON7 Undervoltage Threshold
Def/EE	38h	R/W	MON8 Early Warning Threshold
Def/EE	39h	R/W	MON8 Overvoltage Threshold
Def/EE	3Ah	R/W	MON8 Undervoltage Threshold
Def/EE	3Bh	R/W	MON9 Early Warning Threshold*
Def/EE	3Ch	R/W	MON9 Overvoltage Threshold*
Def/EE	3Dh	R/W	MON9 Undervoltage Threshold*
Def/EE	3Eh	R/W	MON10 Early Warning Threshold*
Def/EE	3Fh	R/W	MON10 Overvoltage Threshold*
Def/EE	40h	R/W	MON10 Undervoltage Threshold*
Def/EE	41h	R/W	MON11 Early Warning Threshold*
Def/EE	42h	R/W	MON11 Overvoltage Threshold*
Def/EE	43h	R/W	MON11 Undervoltage Threshold*
Def/EE	44h	R/W	MON12 Early Warning Threshold*
Def/EE	45h	R/W	MON12 Overvoltage Threshold*
Def/EE	46h	R/W	MON12 Undervoltage Threshold*
Def/EE	47h	R/W	Fault Control
Def/EE	48h	R/W	Faults Causing Emergency EEPROM Save
Def/EE	49h	R/W	Faults Causing Emergency EEPROM Save
Def/EE	4Ah	R/W	Faults Causing Emergency EEPROM Save
Def/EE	4Bh	R/W	Faults Causing Emergency EEPROM Save
Def/EE	4Ch	R/W	Faults Causing Emergency EEPROM Save
Def/EE	4Dh	R/W	Software Enable/MARGIN
Def/EE	4Eh	R/W	Power-Up/Power-Down Pulldown Resistors
Def/EE	4Fh	R/W	Autoretry, Slew Rate, and ADC Fault Deglitch
Def/EE	50h	R/W	Sequence Delays
Def/EE	51h	R/W	Sequence Delays
Def/EE	52h	R/W	Sequence Delays
Def/EE	53h	R/W	Sequence Delays
Def/EE	54h	R/W	Sequence Delays/Reverse-Sequence Bit
Def/EE	55h	R/W	Watchdog Timer Setup
Def/EE	56h	R/W	MON2–MON1 Slot Assignment from Slot 1 to Slot 12
Def/EE	57h	R/W	MON4–MON3 Slot Assignment from Slot 1 to Slot 12
Def/EE	58h	R/W	MON6–MON5 Slot Assignment from Slot 1 to Slot 12
Def/EE	59h	R/W	MON8–MON7 Slot Assignment from Slot 1 to Slot 12
Def/EE	5Ah	R/W	MON10–MON9 Slot Assignment from Slot 1 to Slot 12*

### Register Map (continued)

PAGE	ADDRESS	READ/WRITE	DESCRIPTION
Def/EE	5Bh	R/W	MON12–MON11 Slot Assignment from Slot 1 to Slot 12*
Def/EE	5Ch	R/W	Customer Firmware Version
Def/EE	5Dh	R/W	EEPROM and Configuration Lock
Def/EE	5Eh	R/W	EN_OUT2-EN_OUT1 Slot Assignment from Slot 0 to Slot 11
Def/EE	5Fh	R/W	EN_OUT4-EN_OUT2 Slot Assignment from Slot 0 to Slot 11
Def/EE	60h	R/W	EN_OUT6-EN_OUT5 Slot Assignment from Slot 0 to Slot 11
Def/EE	61h	R/W	EN_OUT8-EN_OUT7 Slot Assignment from Slot 0 to Slot 11
Def/EE	62h	R/W	EN_OUT10-EN_OUT9 Slot Assignment from Slot 0 to Slot 11*
Def/EE	63h	R/W	EN_OUT12-EN_OUT11 Slot Assignment from Slot 0 to Slot 11*
Def/EE	64h	R/W	INS Power-Good (PG) Thresholds
Def/EE	65h	R	Manufacturing Revision Code
Def/EE	66h–93h	_	Reserved
EEPROM	9Ch-FFh	R/W	User EEPROM

<sup>\*</sup>MAX16047A only

Note: Ext refers to registers contained in the extended page, Default refers to registers contained in the default page, EEPROM refers to EEPROM memory locations, and Def/EE refers to locations that are stored in EEPROM and loaded into the same addresses in the default page on boot-up.

### **Selector Guide**

PART	VOLTAGE DETECTOR INPUTS	GENERAL-PURPOSE INPUTS/OUTPUTS	SEQUENCING OUTPUTS
MAX16047ATN+	12	6	12
MAX16049ATN+	8	6	8

### **Chip Information**

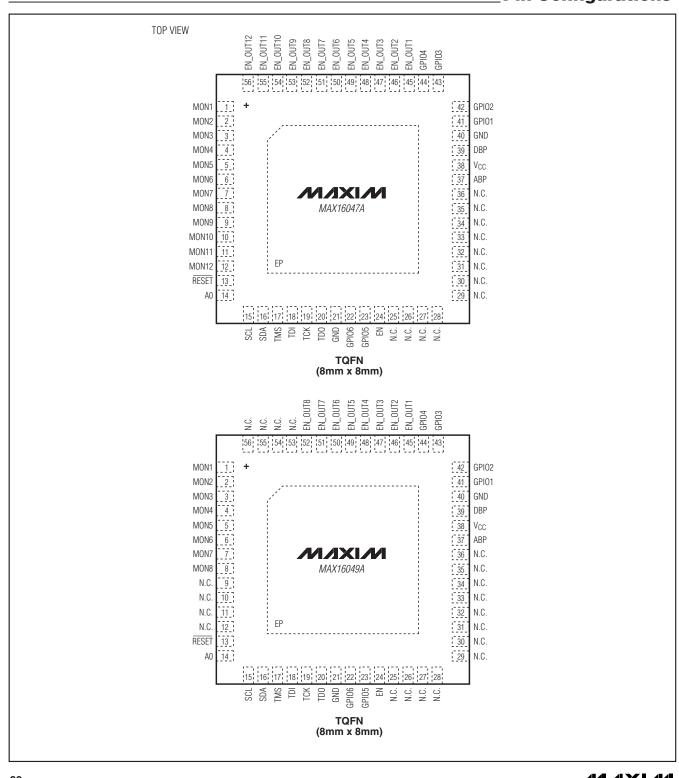
### **Package Information**

For the latest package outline information and land patterns, go to www.maxim-ic.com/packages. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

PACKAGE TYPE	PACKAGE CODE	OUTLINE NO.	LAND PATTERN NO.
56 TQFN	T5688+3	<u>21-0135</u>	90-0047

PROCESS: BICMOS

**Pin Configurations** 



### **Revision History**

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	4/10	Initial release	_
1	9/10	Added text to the Enable, Instruction Register, and Device Behavior at Power-Up sections, style edits, updated Package Information	16, 48, 53, 59

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